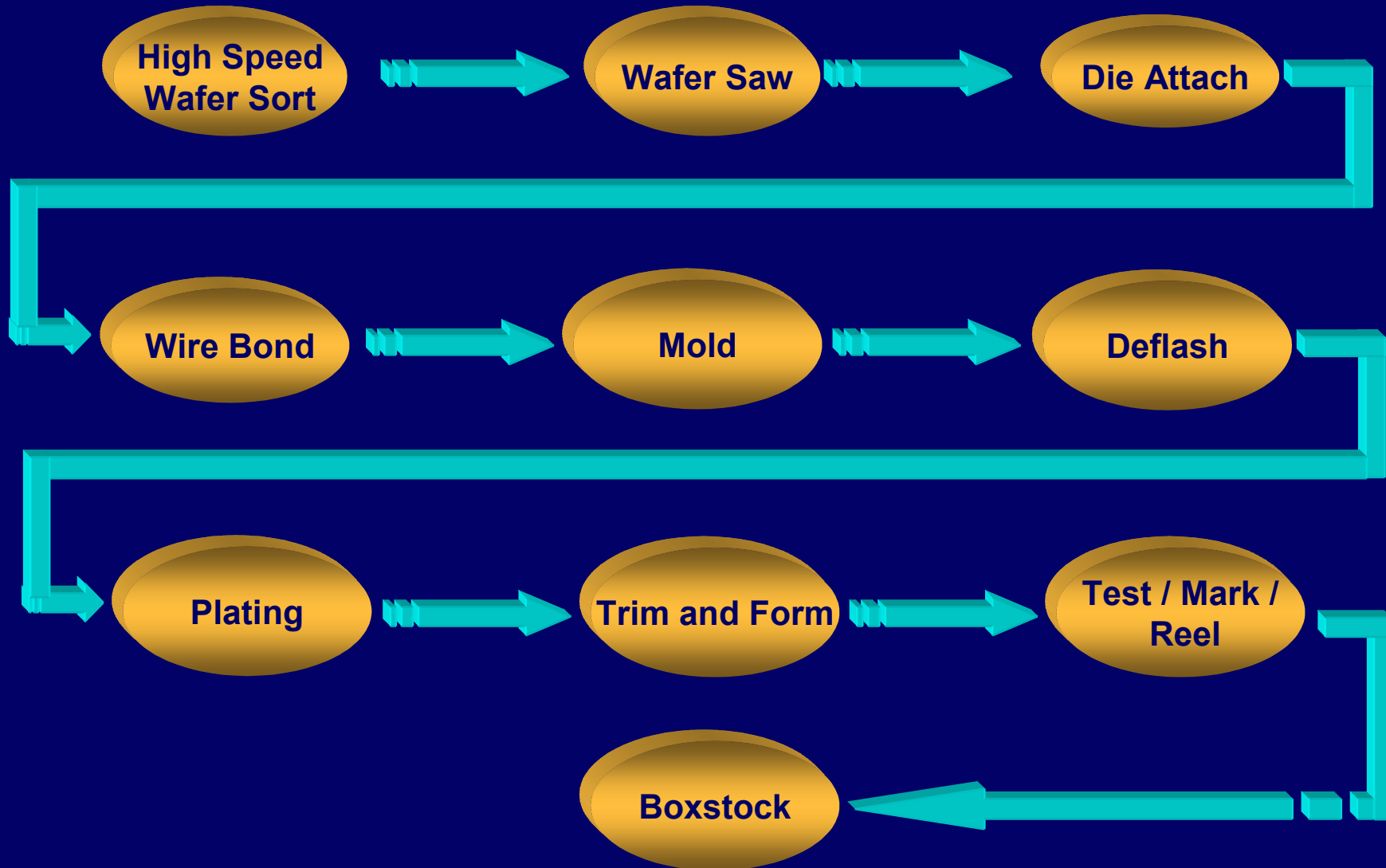


EXIT

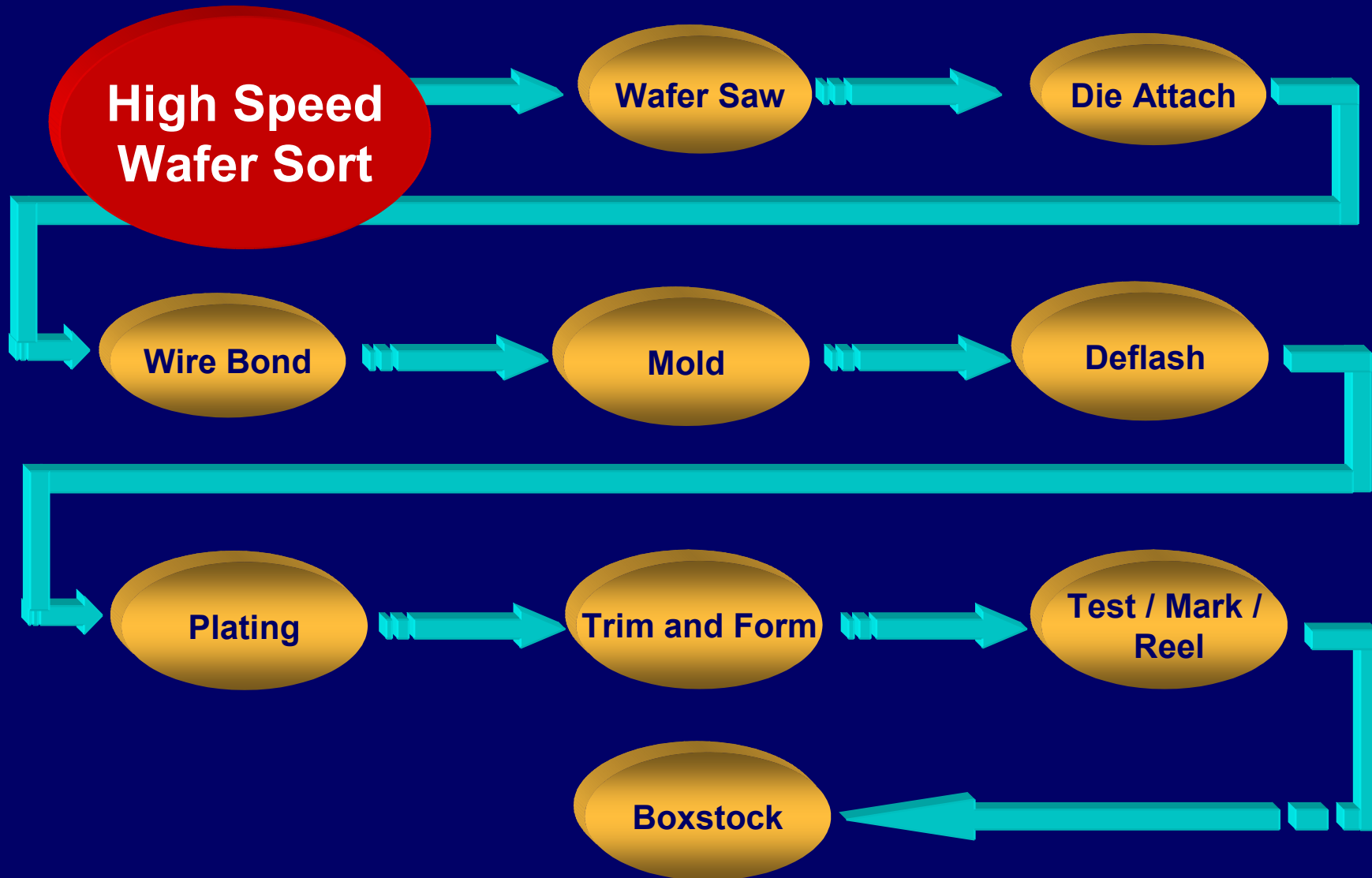
Semiconductor Assembling Process



Manufacturing Technology

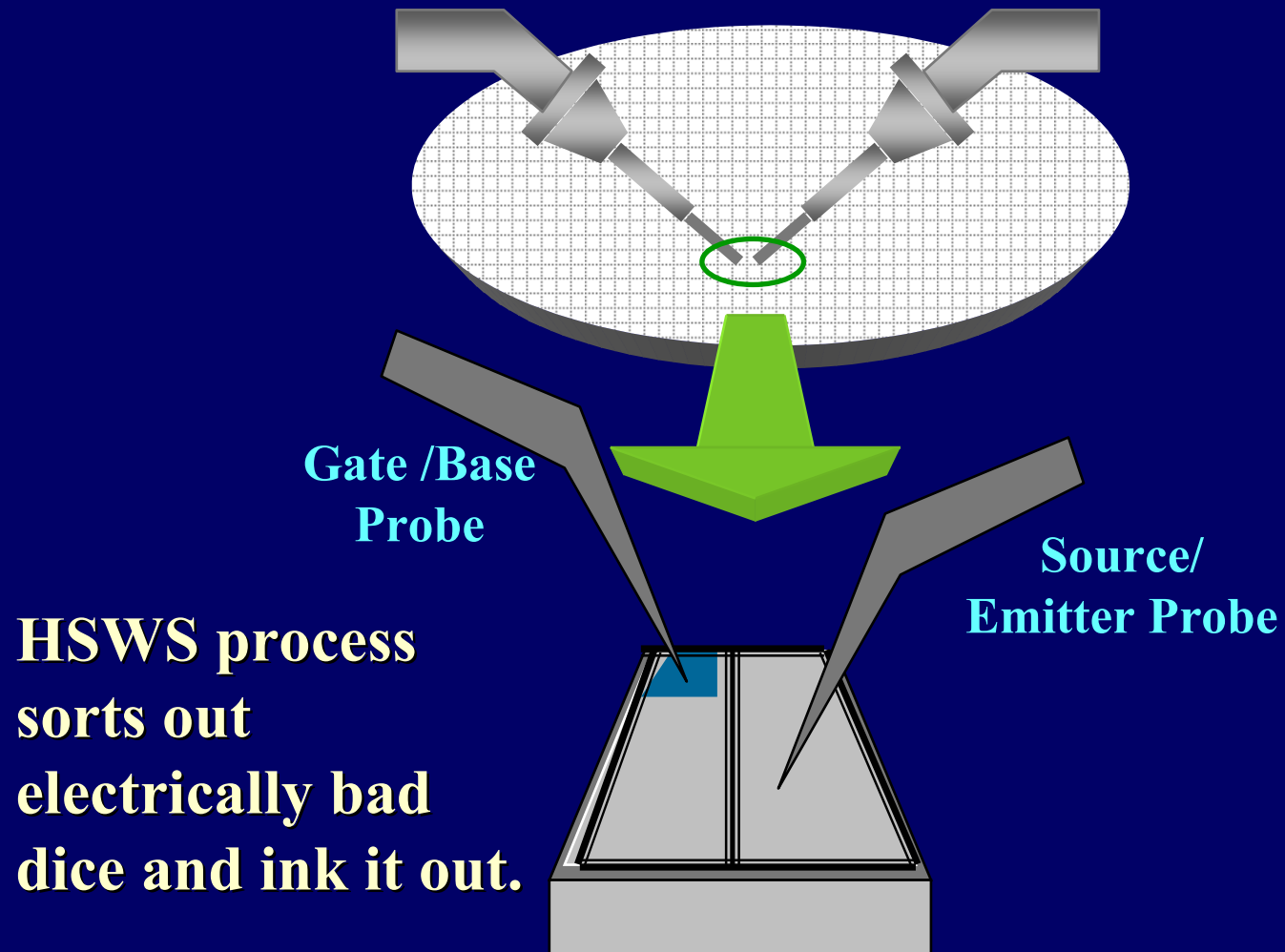


Manufacturing Technology

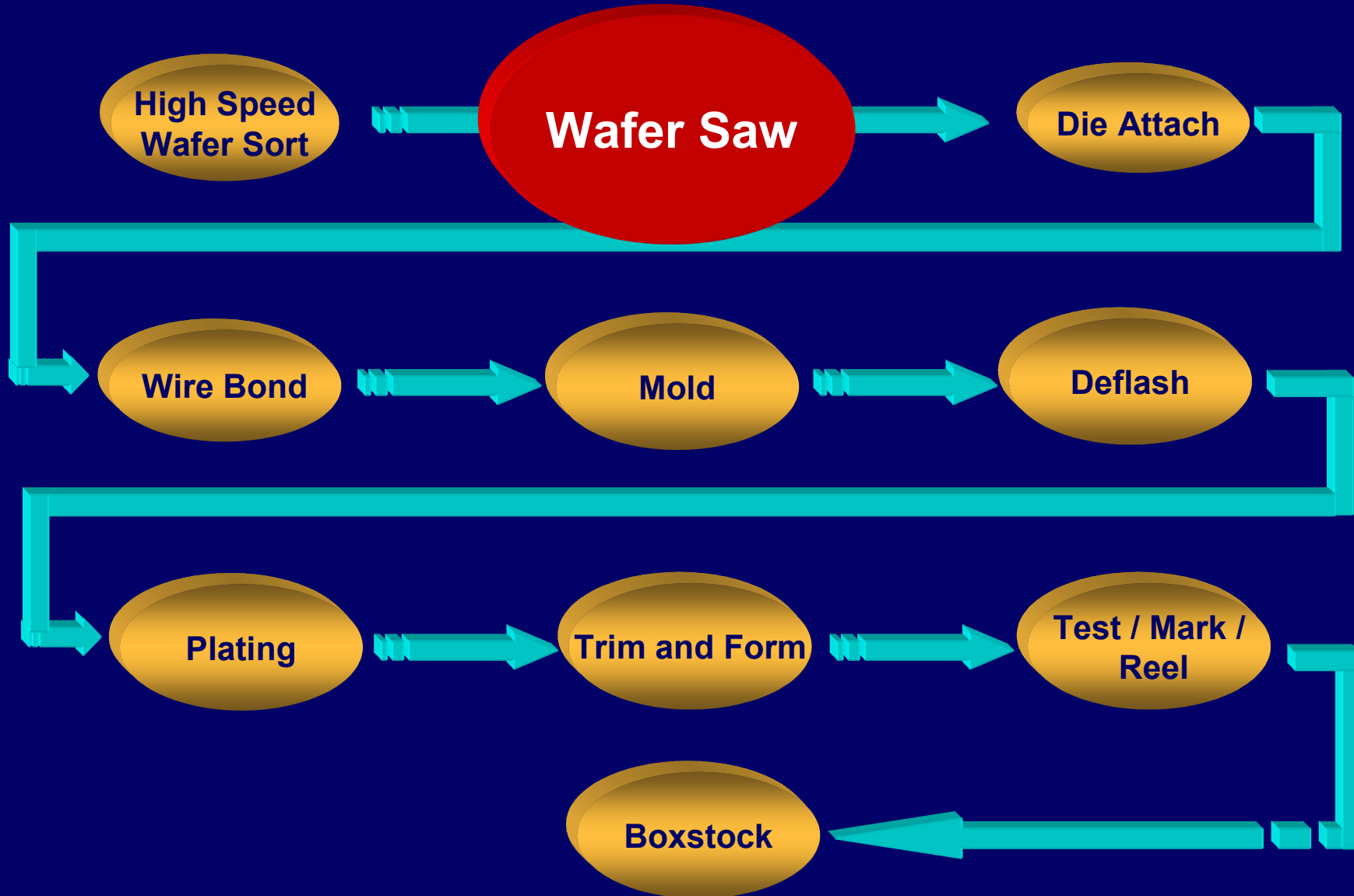


High Speed Wafer Sort

Semiconductor Manufacturing Process

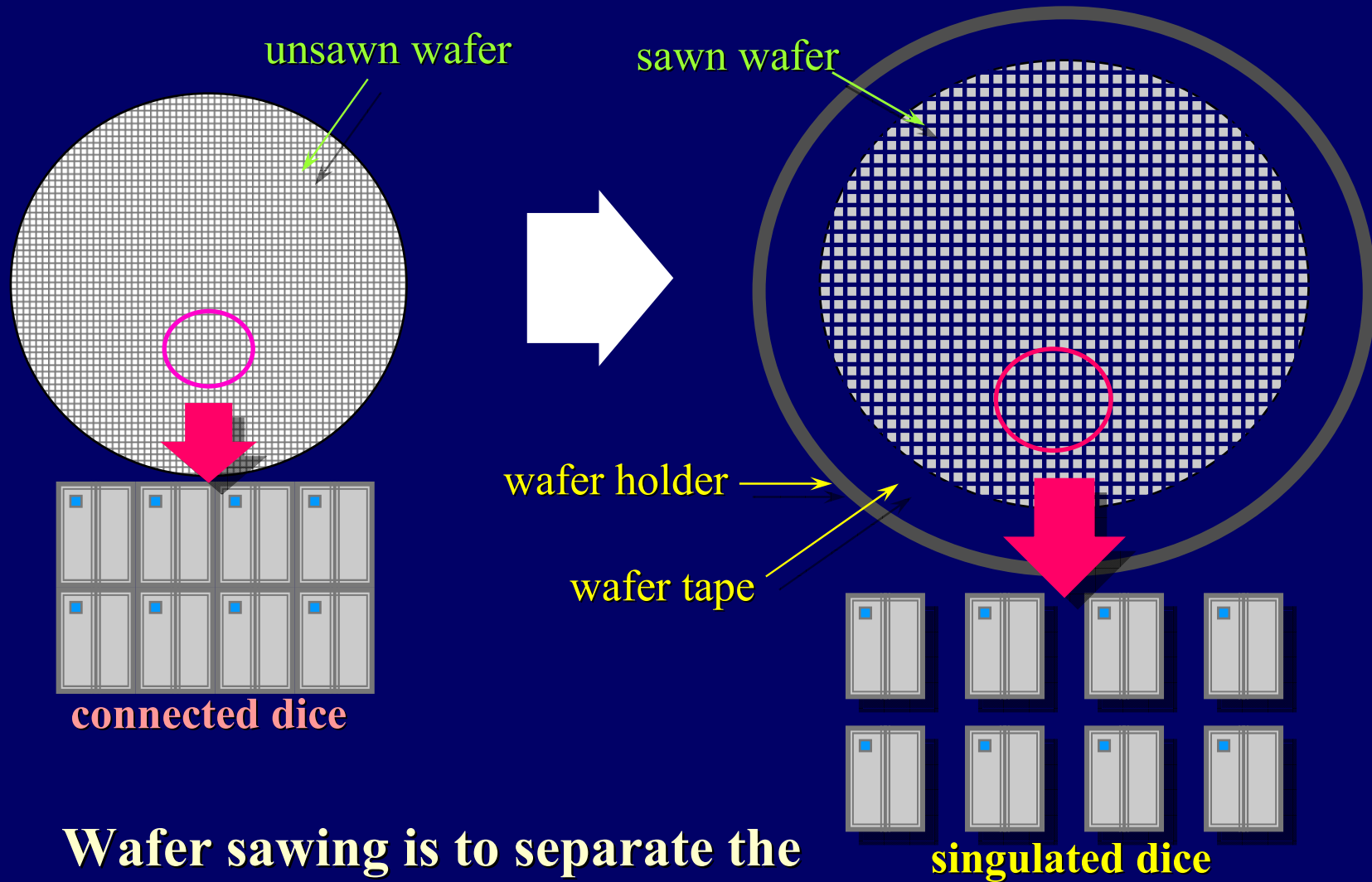


Manufacturing Technology



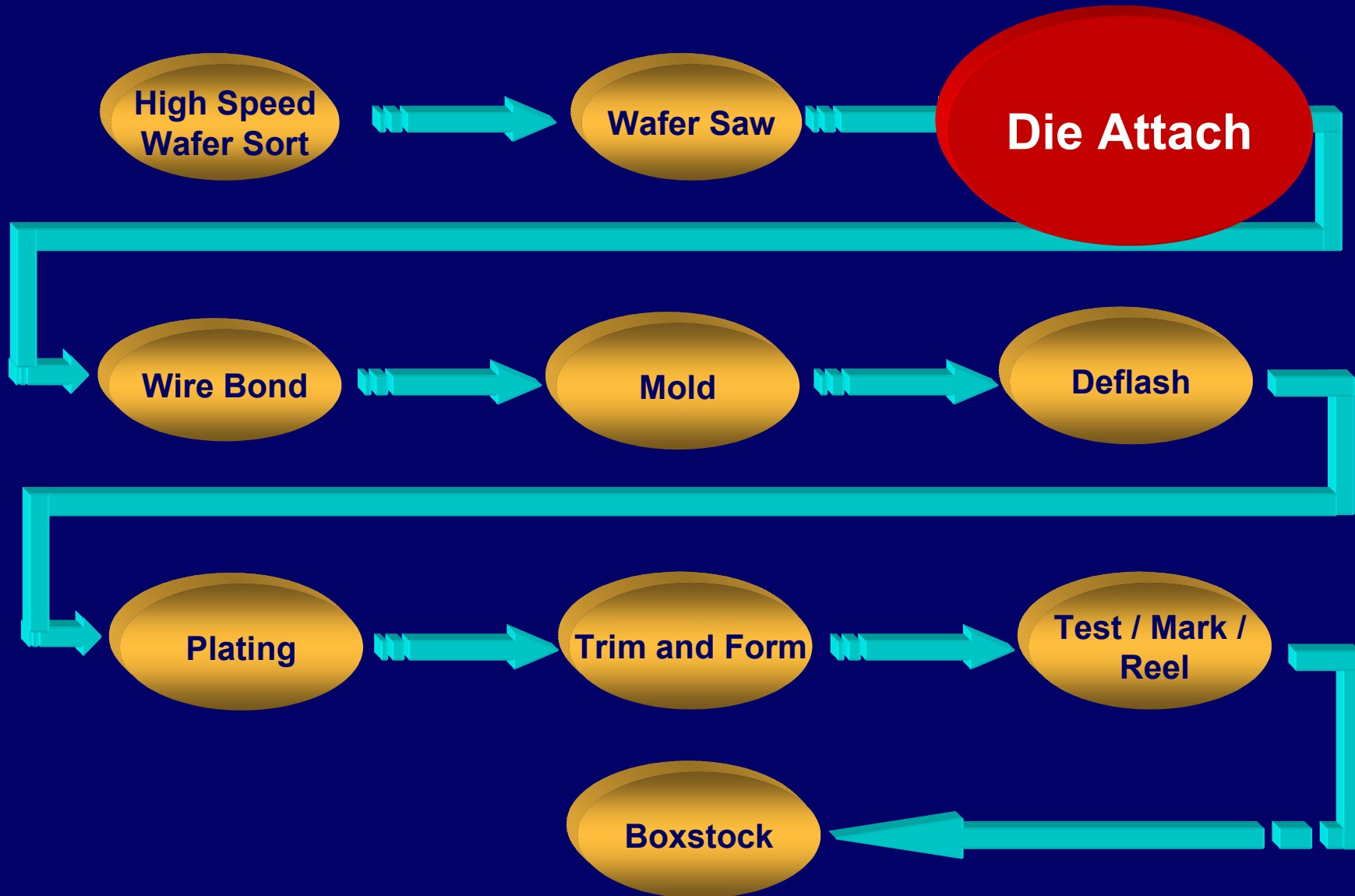
DICING / WAFER SAWING

Semiconductor Manufacturing Process



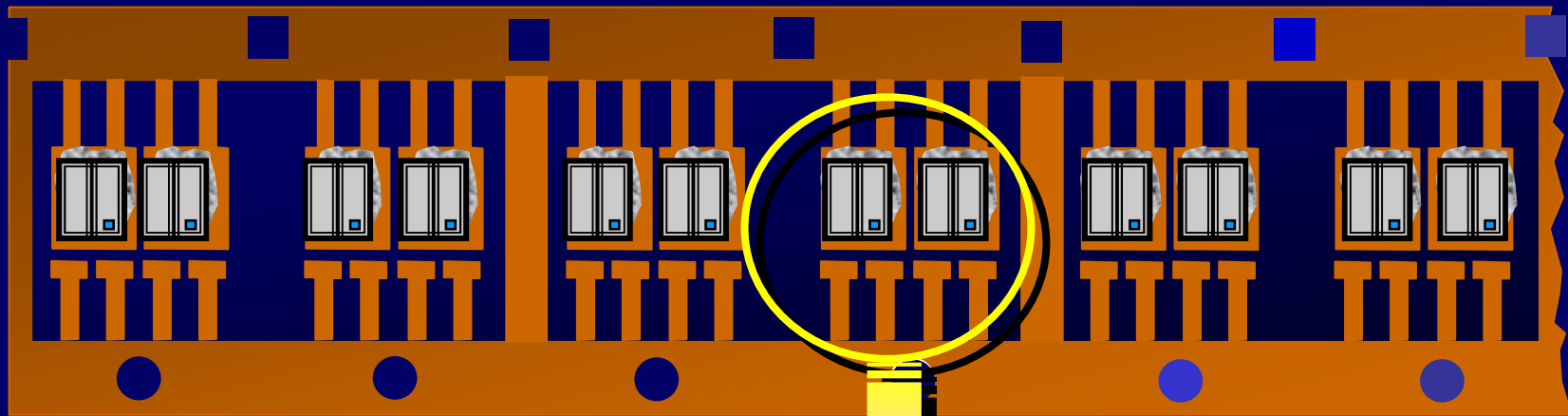
Wafer sawing is to separate the dice in wafer into individual chips.

Manufacturing Technology



Die Attach

Semiconductor Manufacturing Process

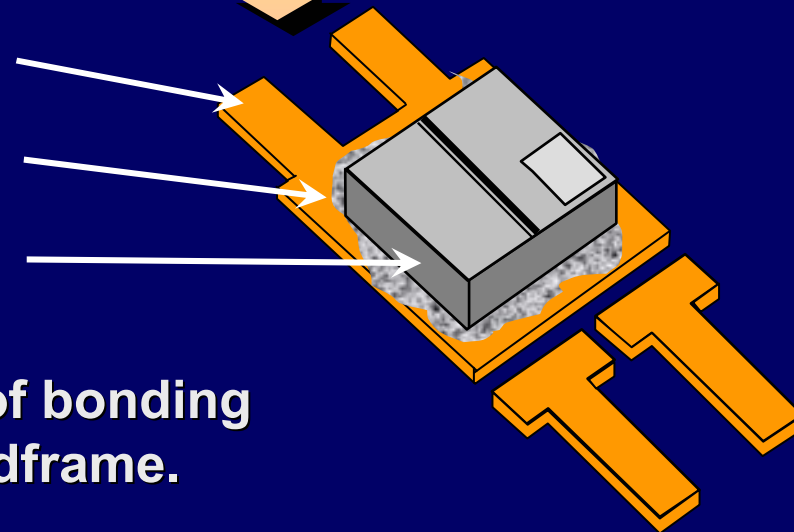


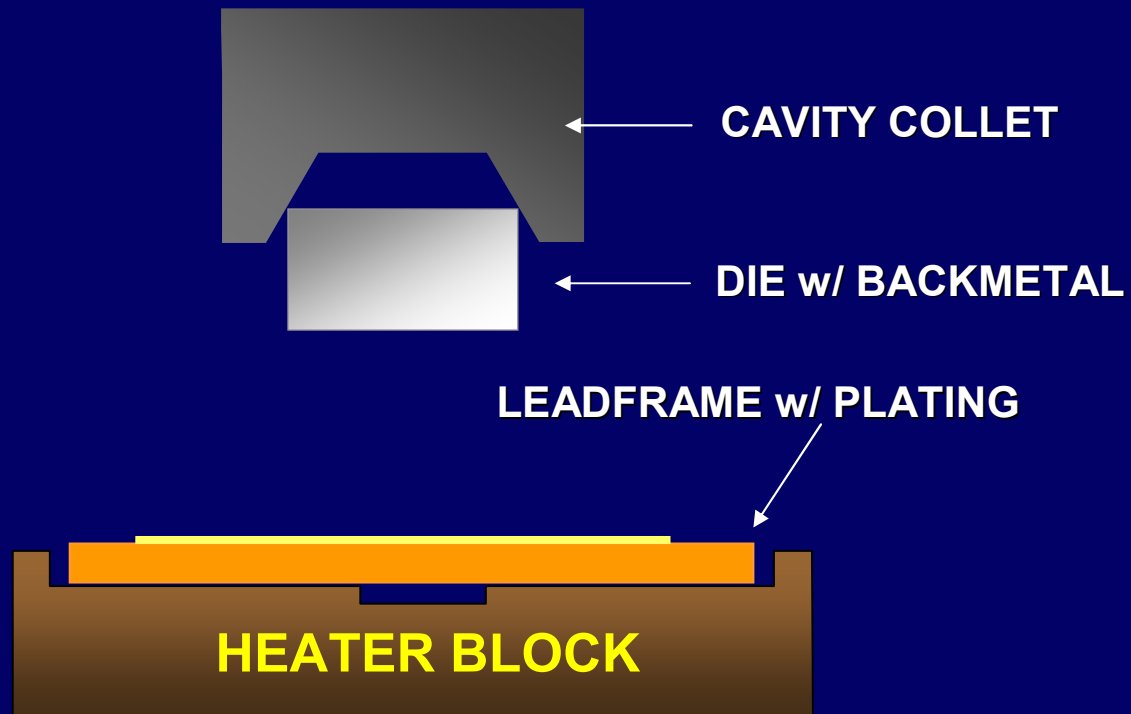
Cu Leadframe

Die Attach Material

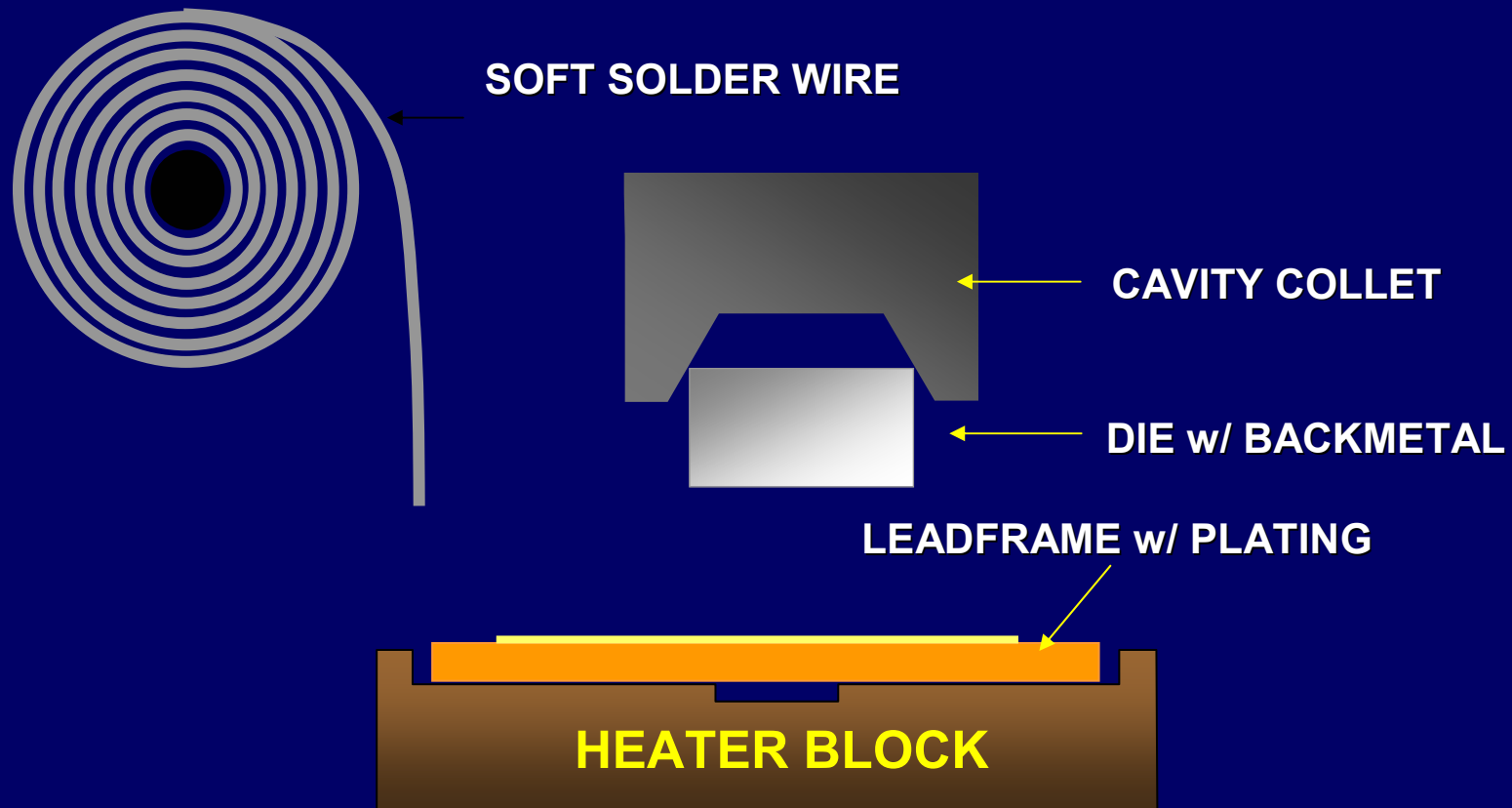
Die or Microchip

Die Attach is a process of bonding the microchip on the leadframe.



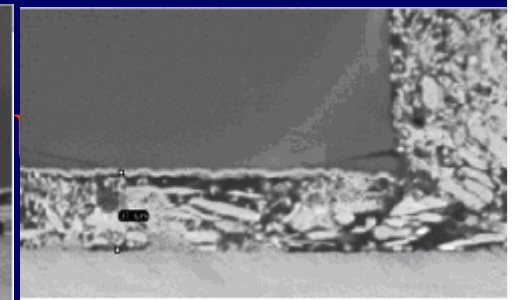
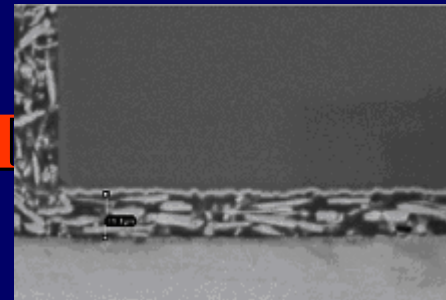
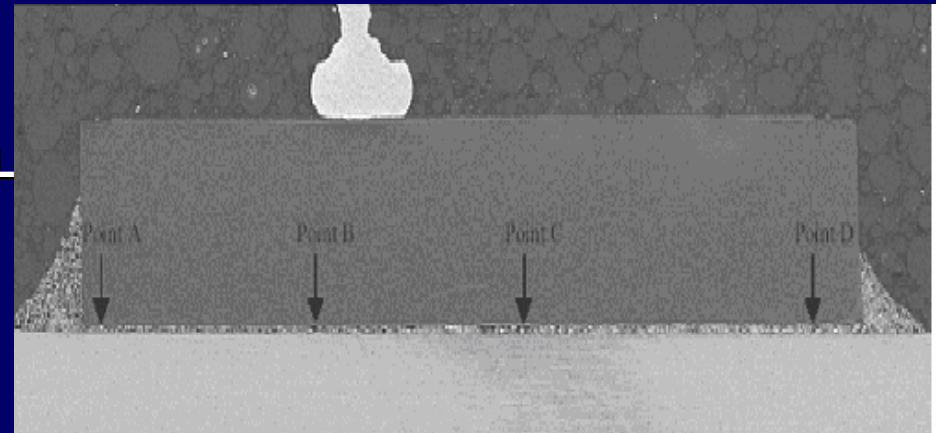
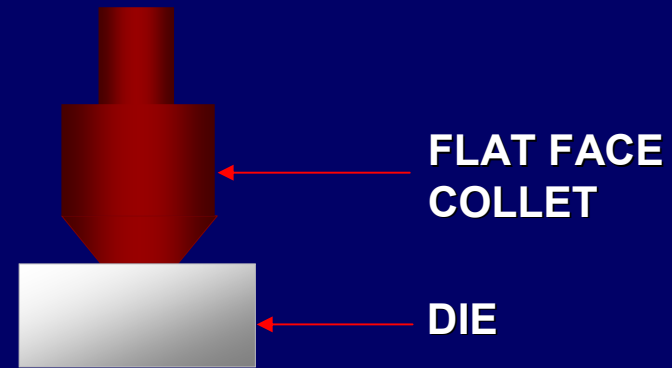
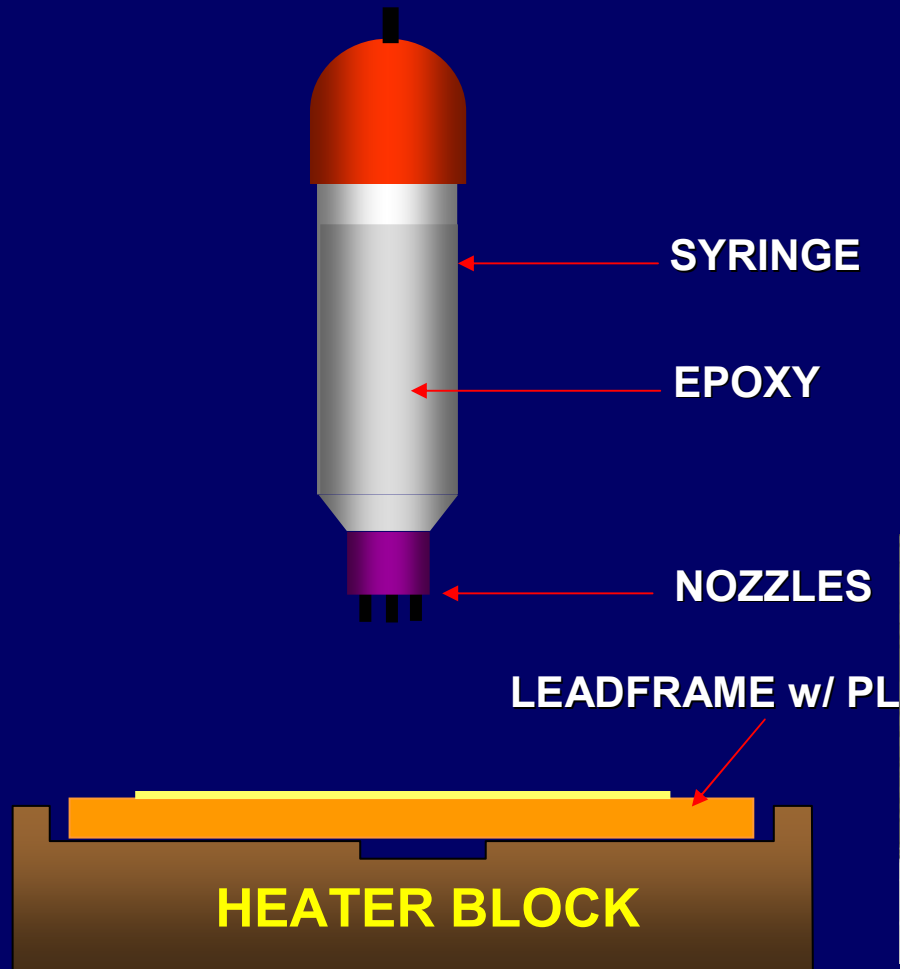


EUTECTIC DIE ATTACH SET-UP



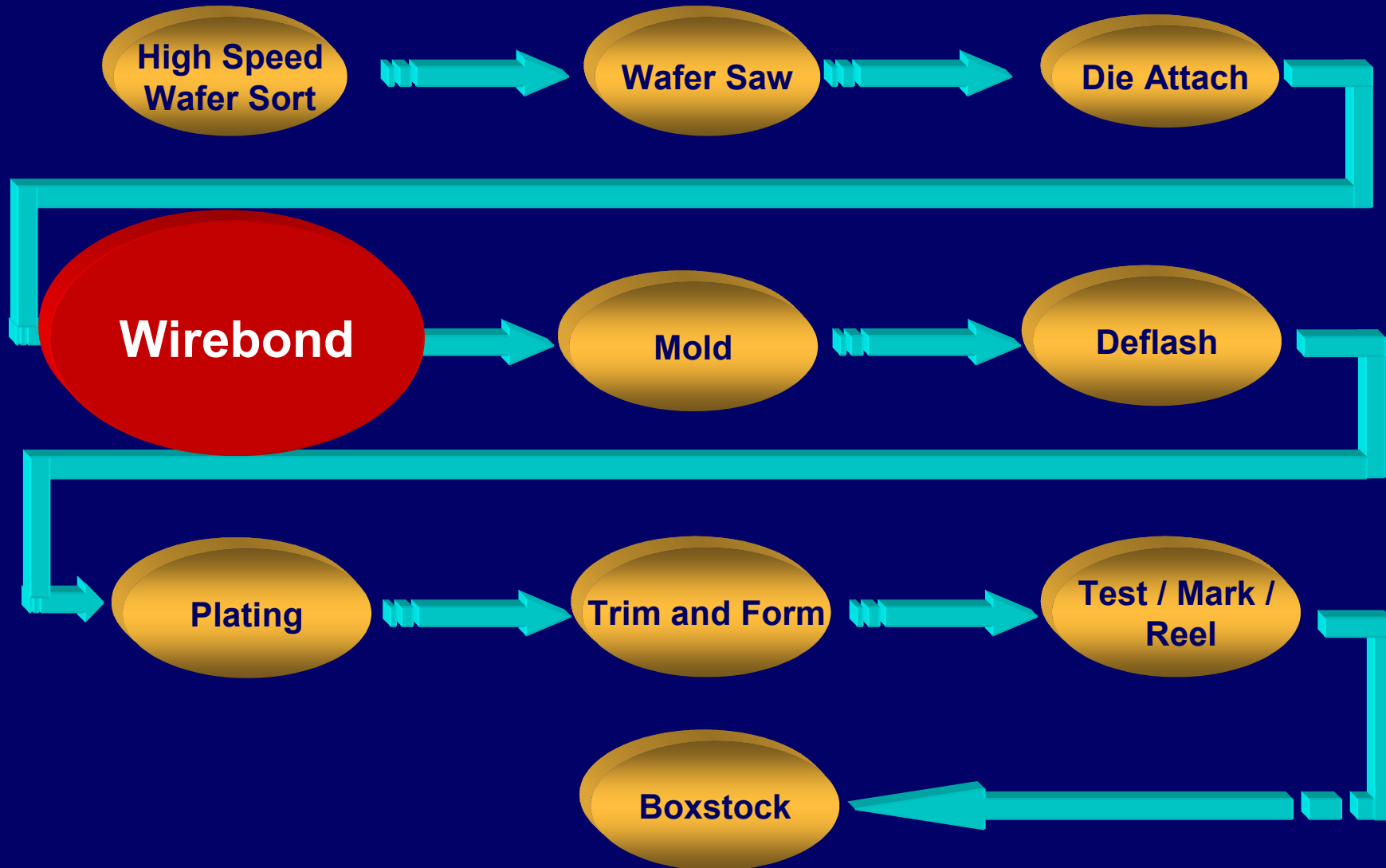
SOFT SOLDER DIE ATTACH SET-UP

Semiconductor Manufacturing Process



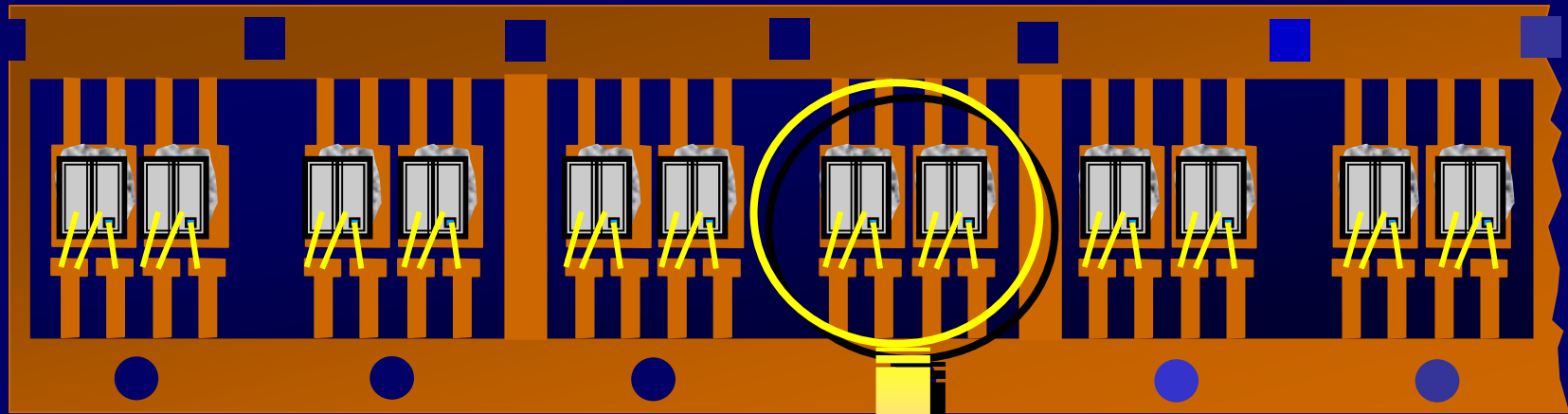
EPOXY DIE AT

Manufacturing Technology



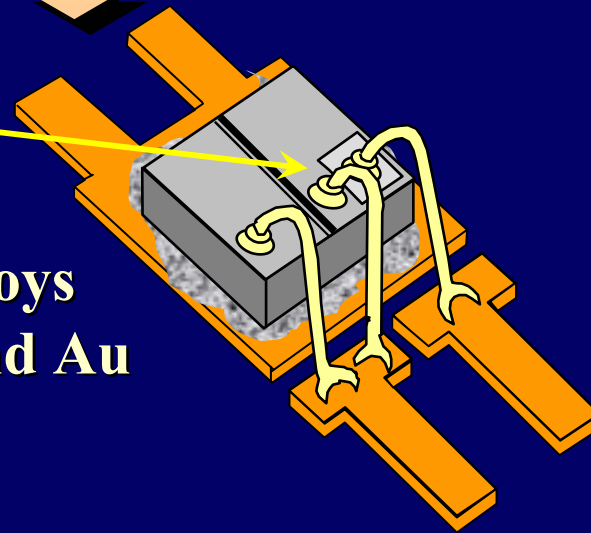
Thermosonic Wirebond

Semiconductor Manufacturing Process

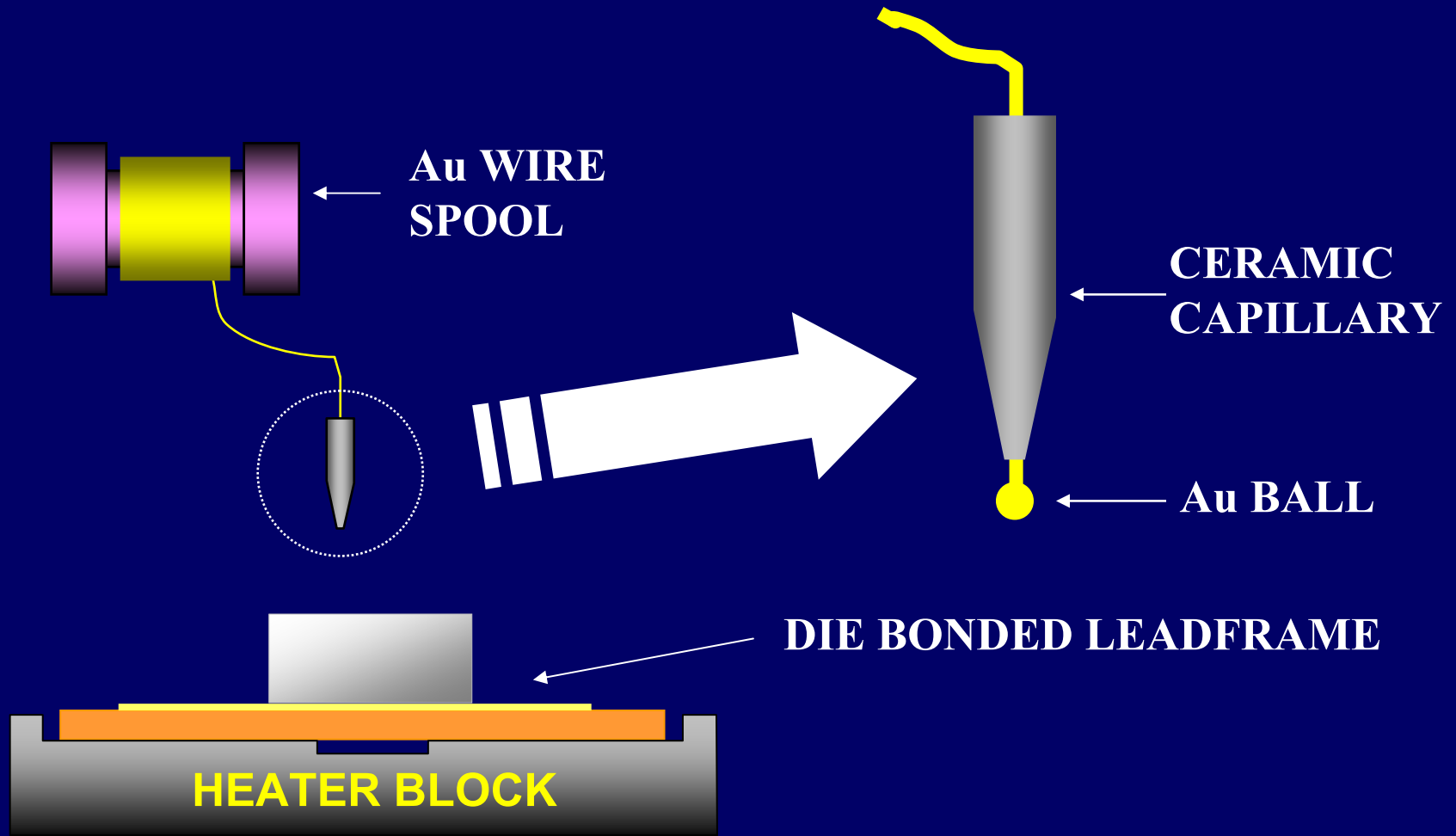


99.99% Gold wires

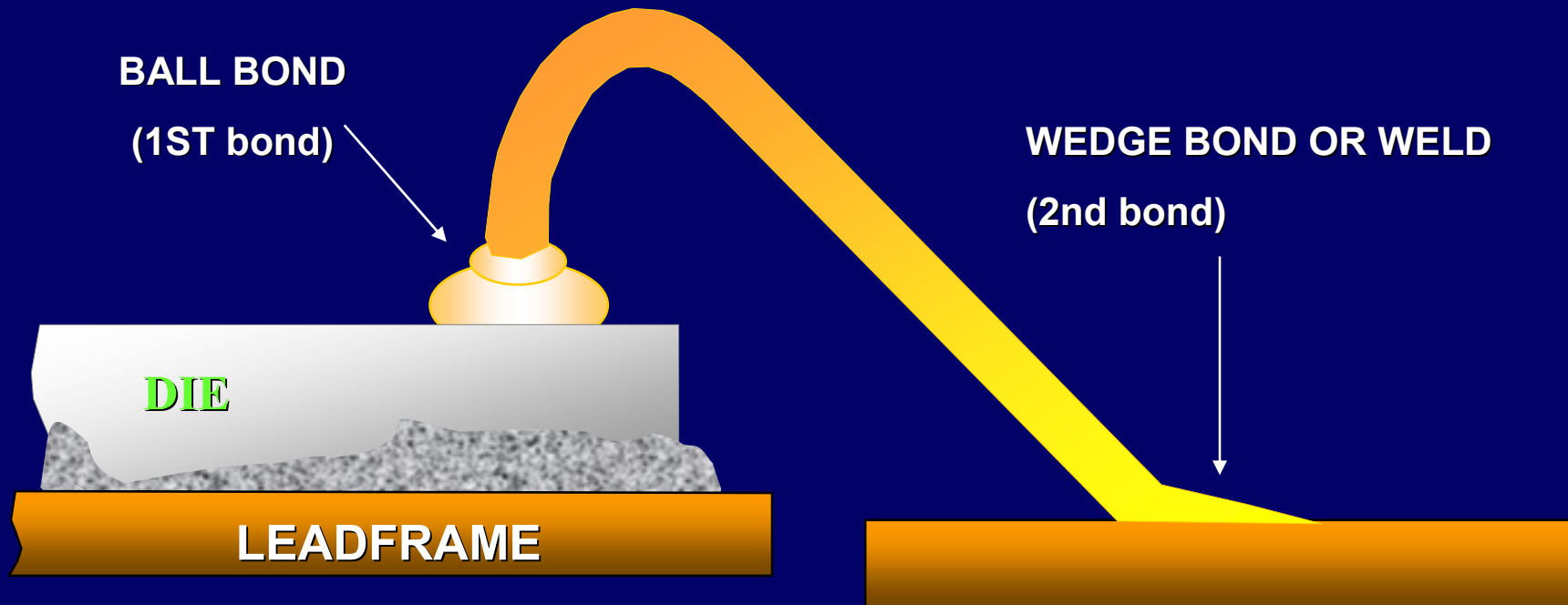
Thermosonic wire bonding employs heat and ultrasonic power to bond Au wire on die surface.



Semiconductor Manufacturing Process

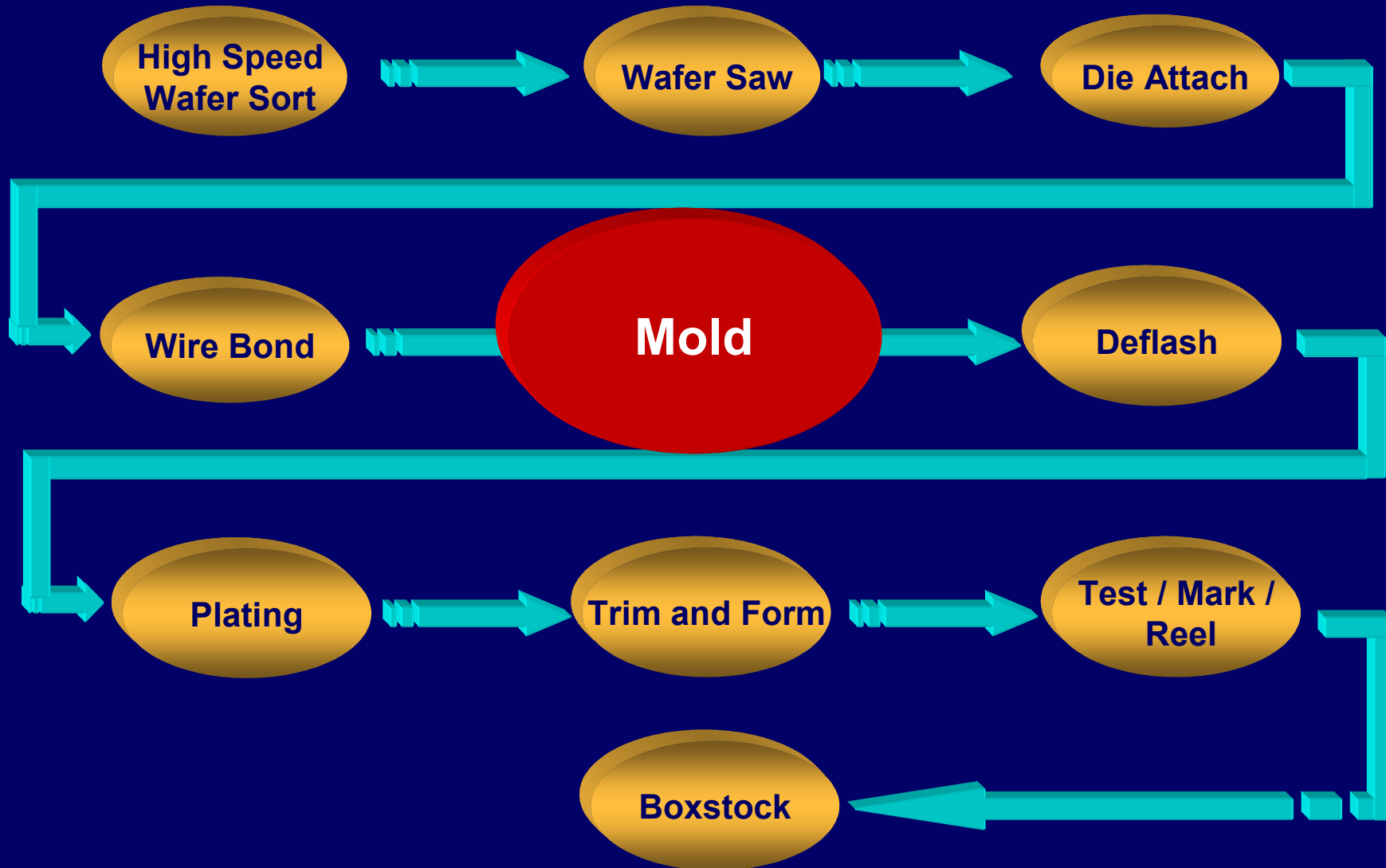


THERMOSONIC WIREBOND SET-UP



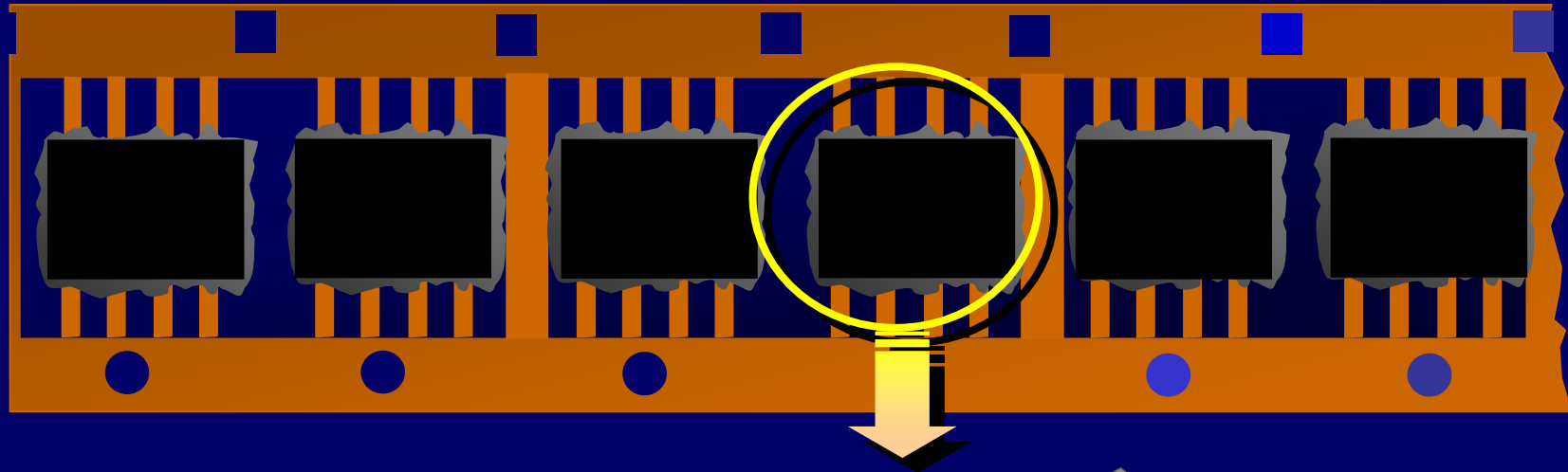
WIREBONDS

Manufacturing Technology

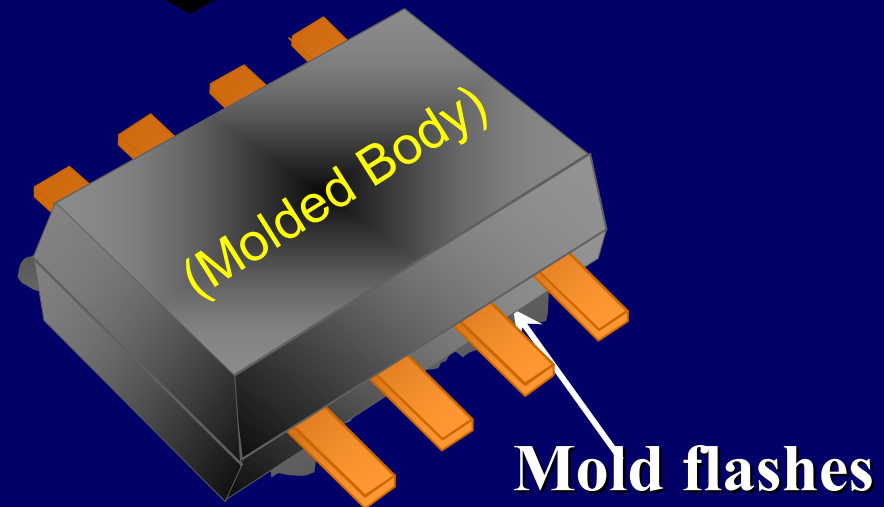


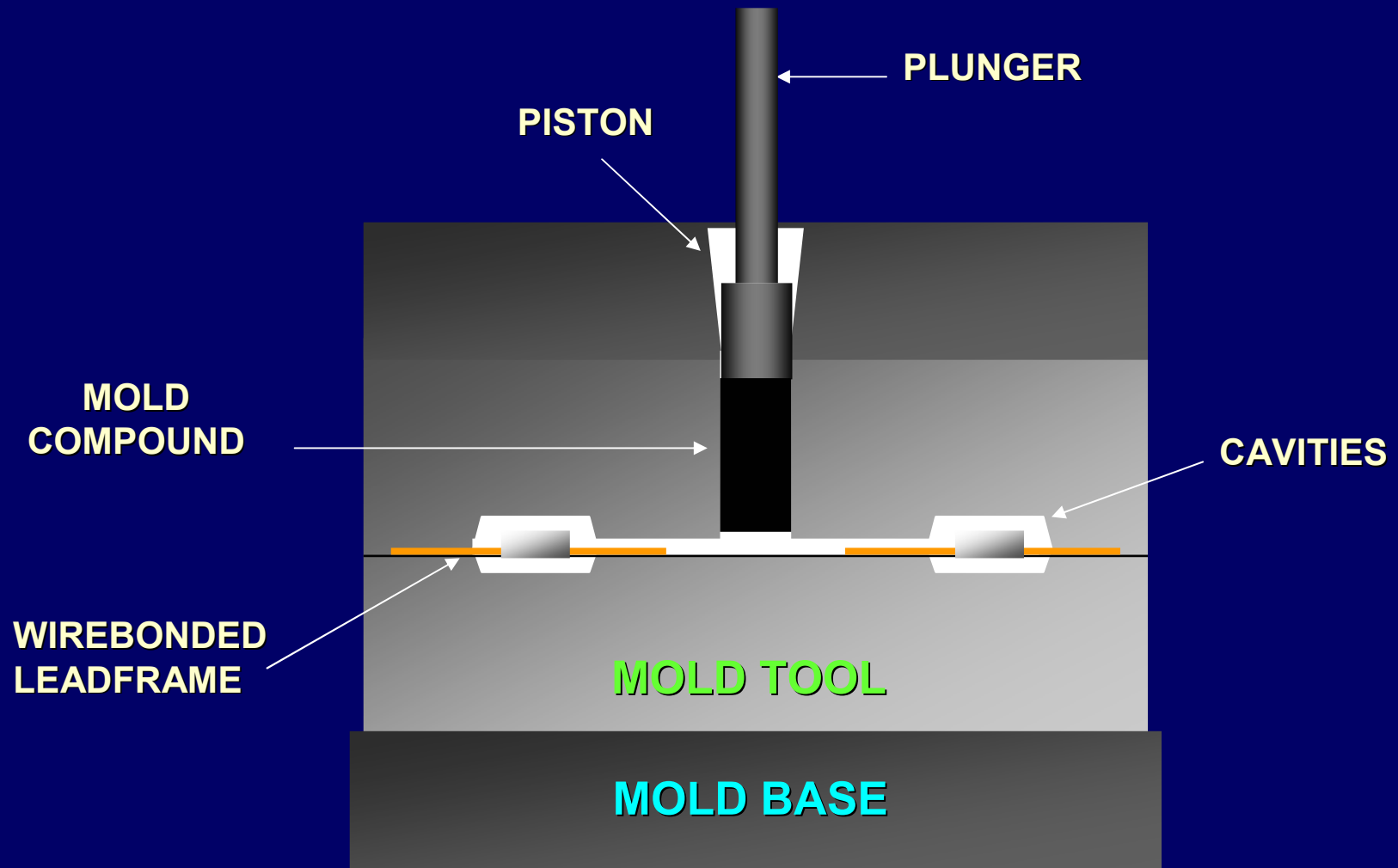
Transfer Molding

Semiconductor Manufacturing Process

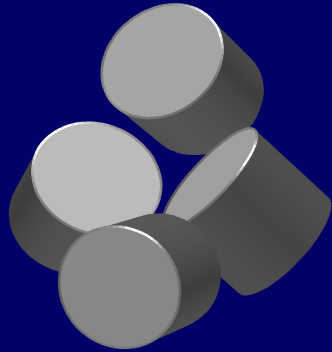


Transfer molding is a process of encapsulating the wirebonded microchip. It gives the package its distinct shape.

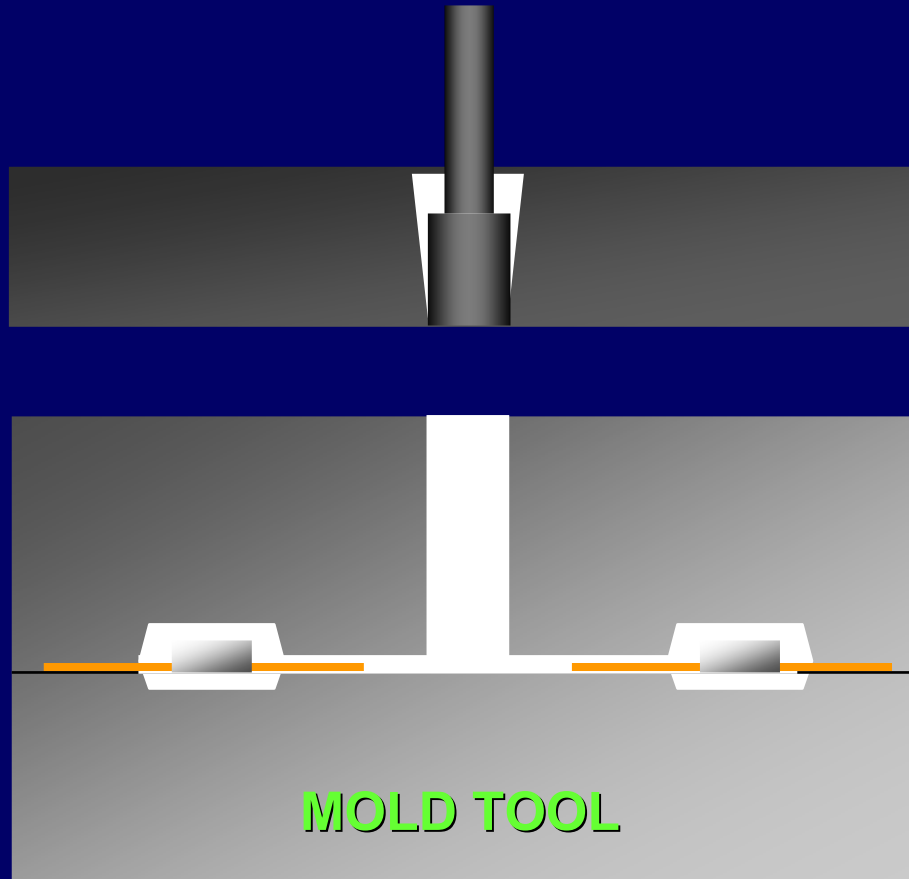




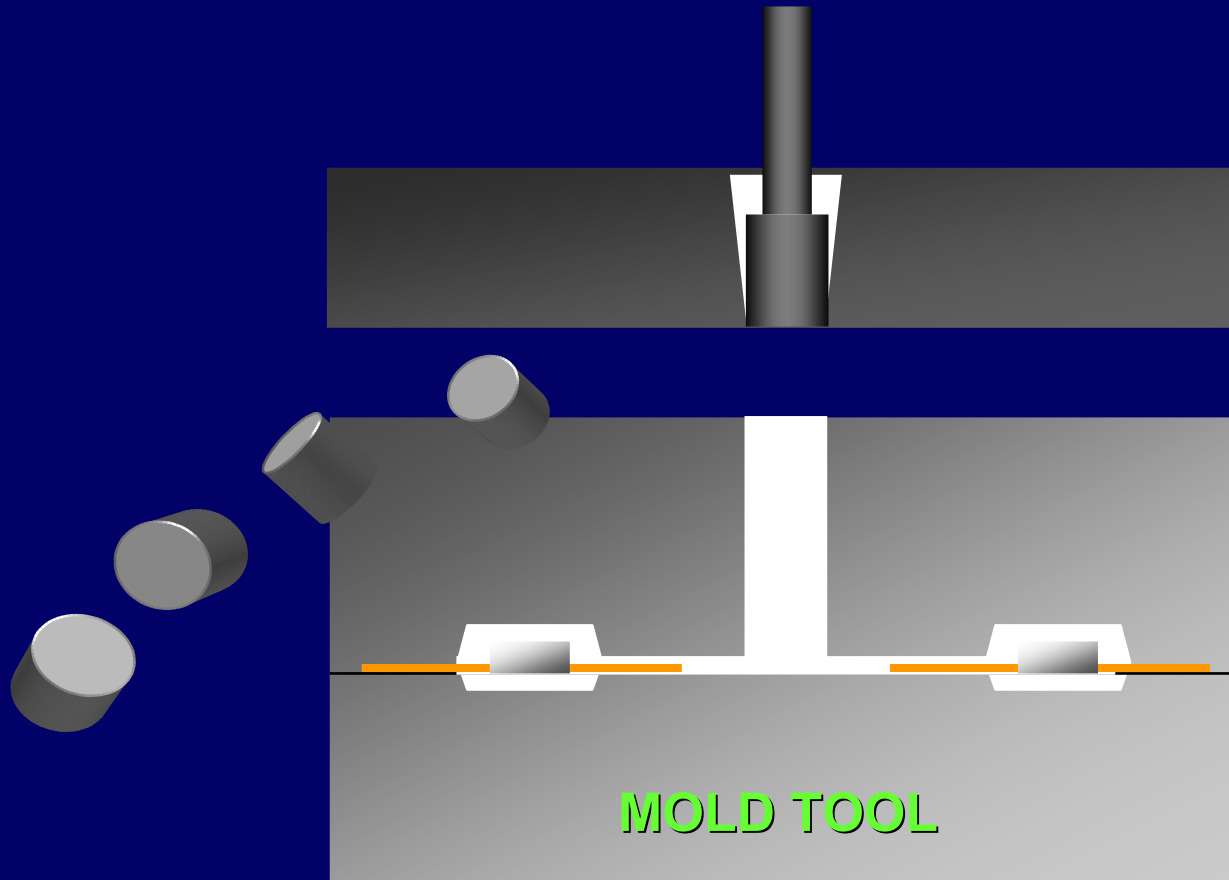
TRANSFER MOLDING SET-UP



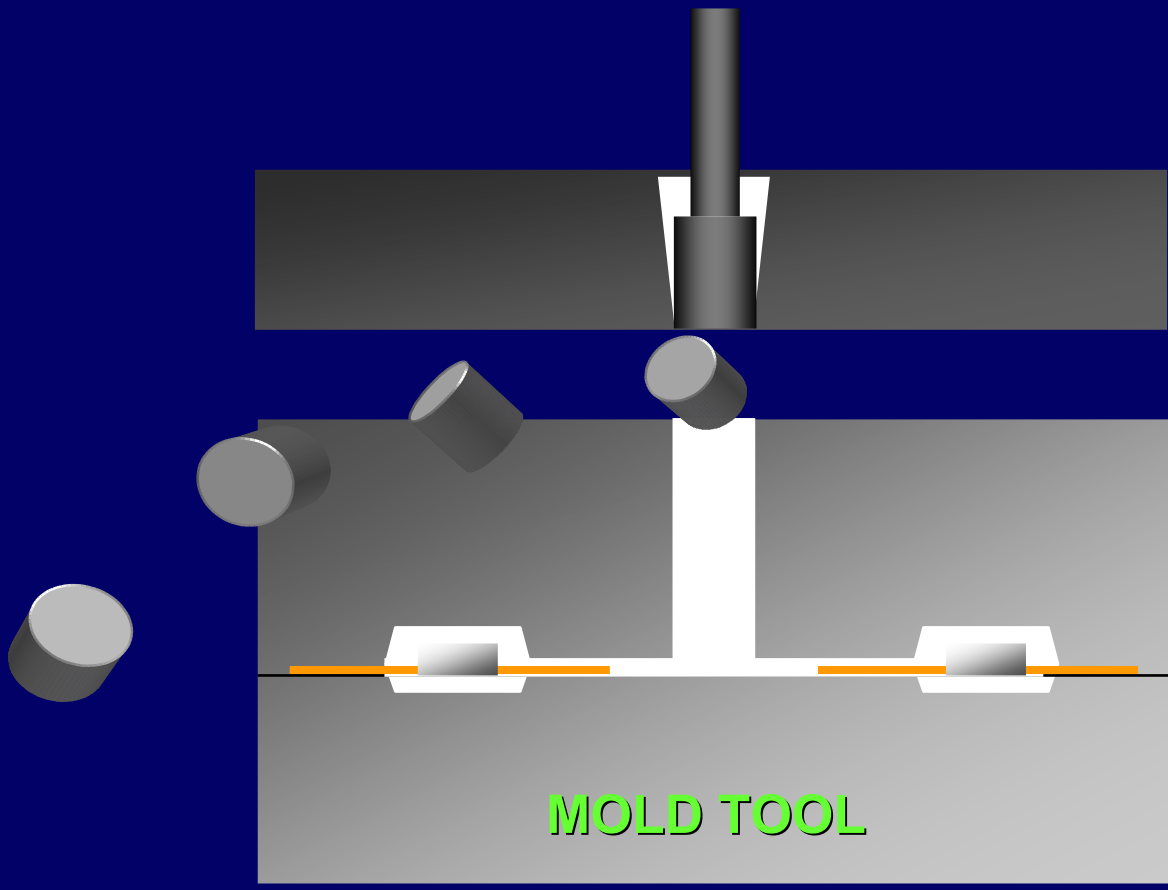
**MOLD COMPOUND
PELLETS**



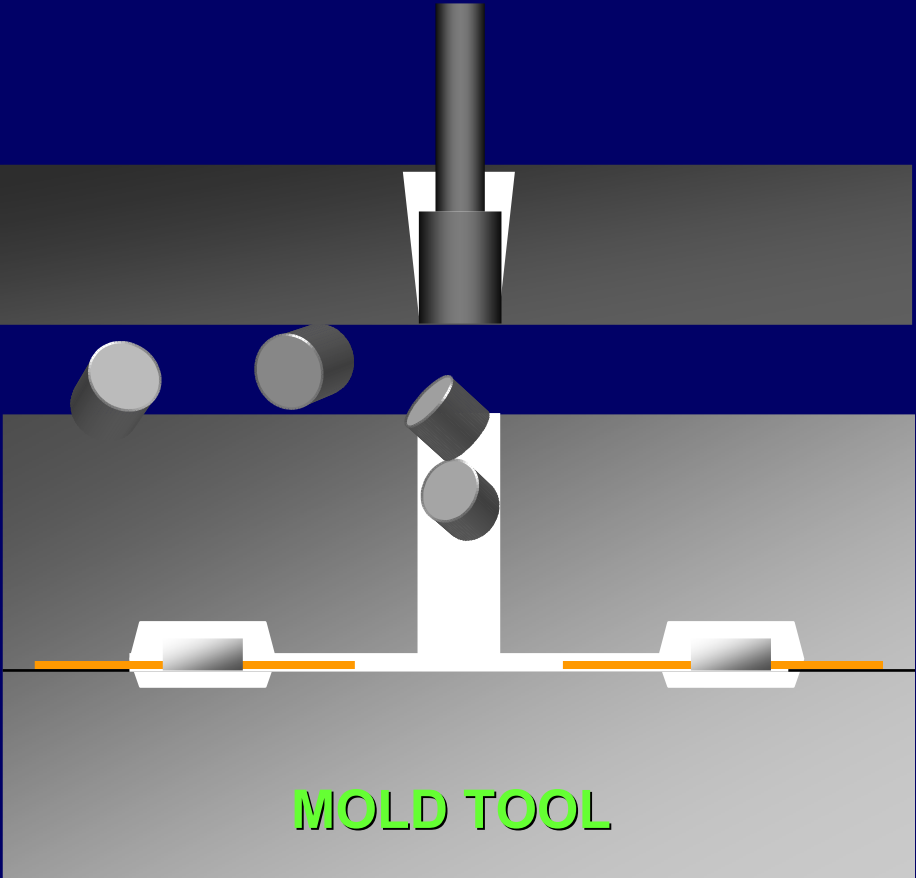
MOLD TOOL

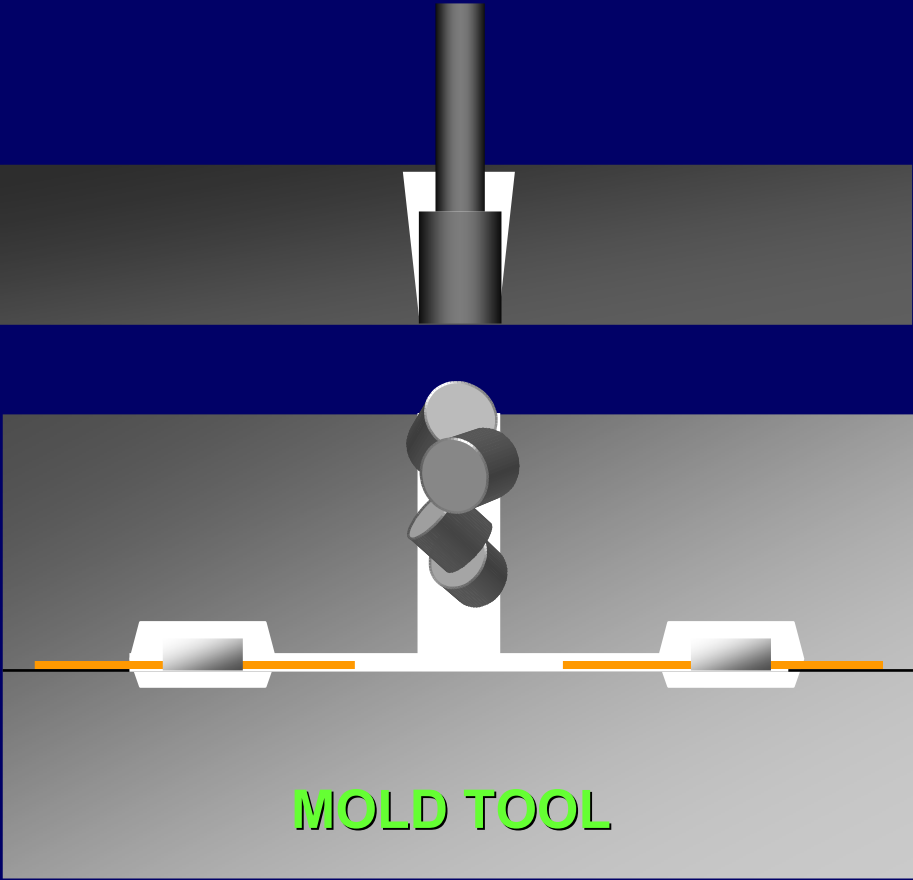


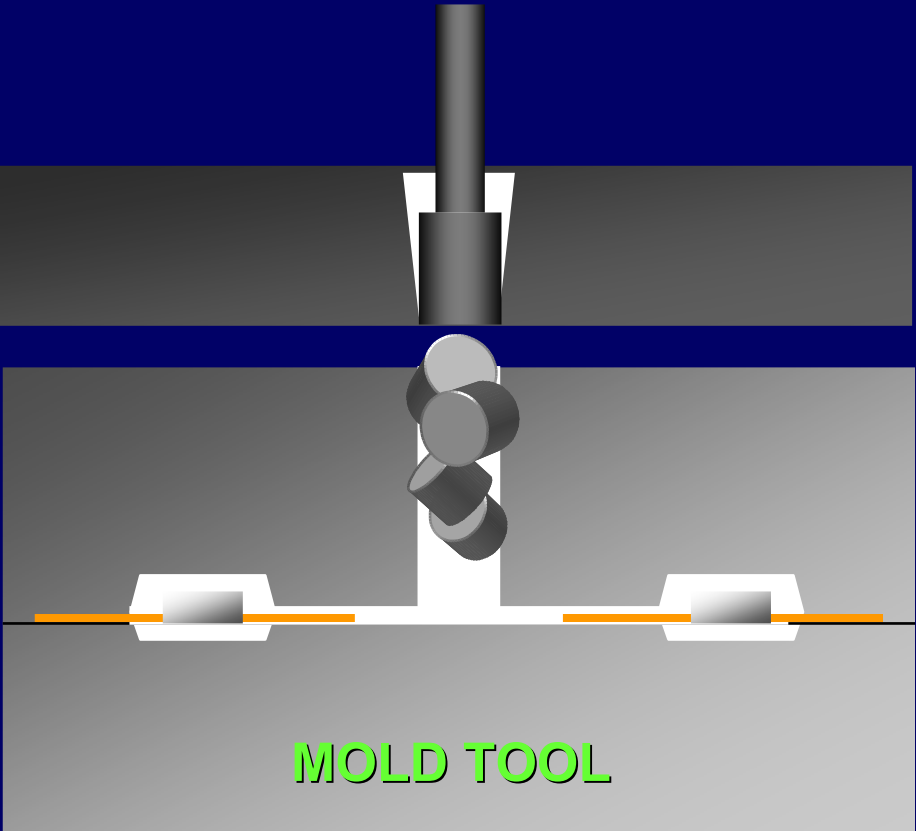
MOLD TOOL

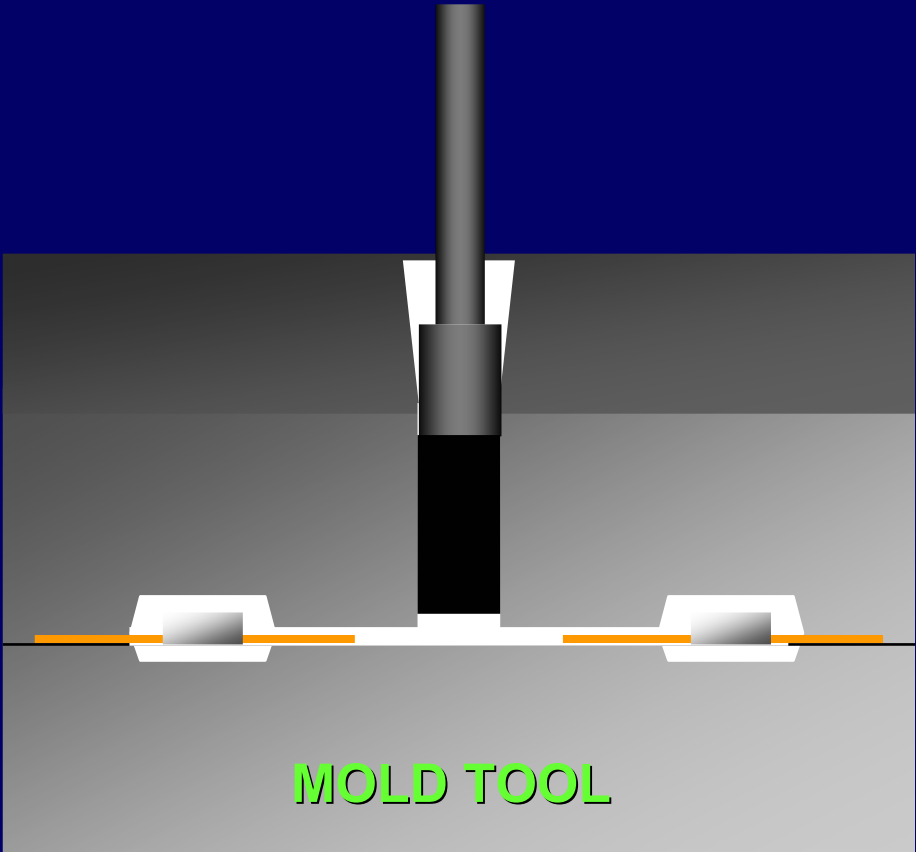


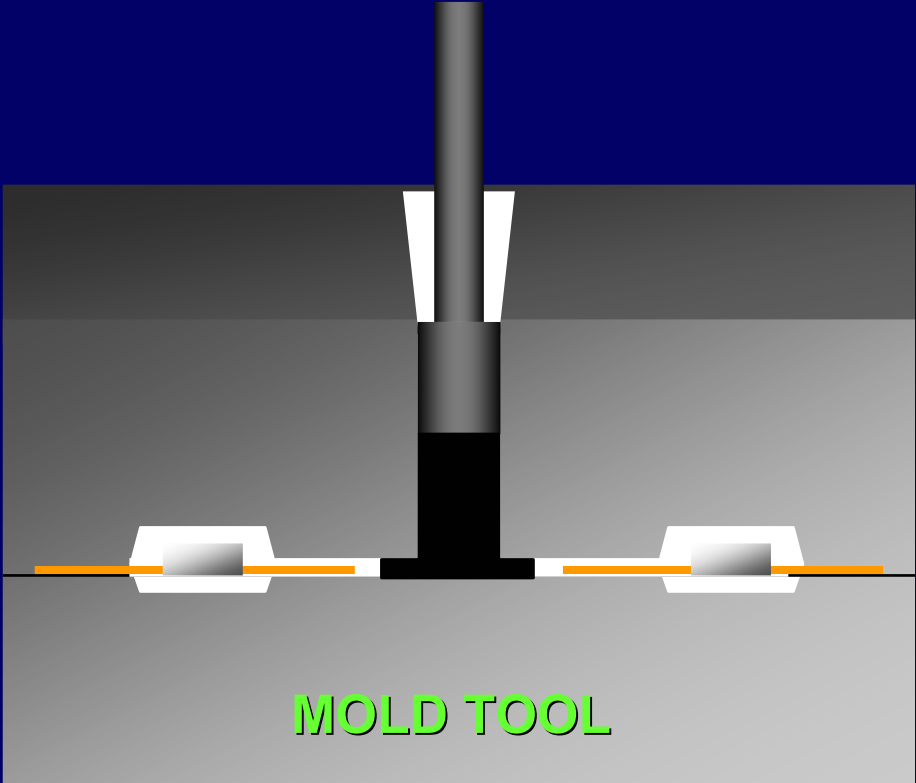
MOLD TOOL

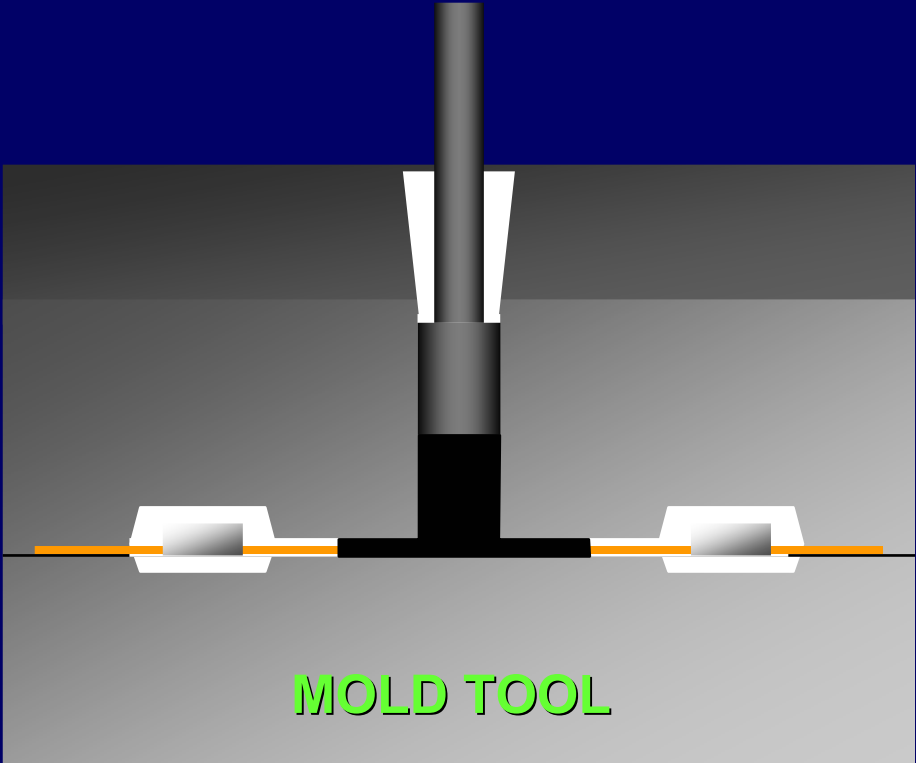


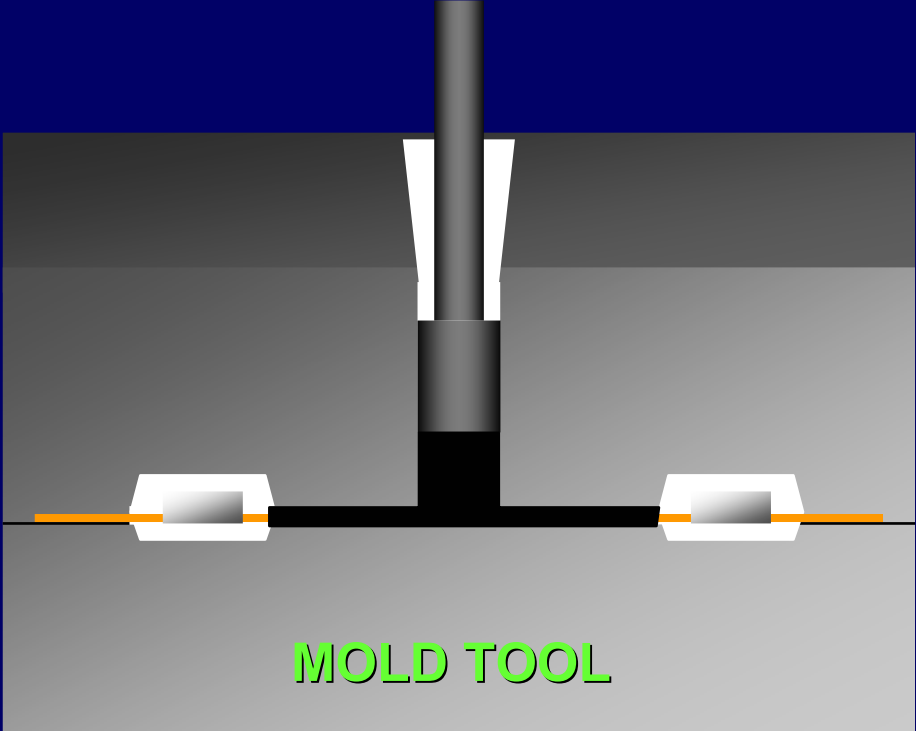


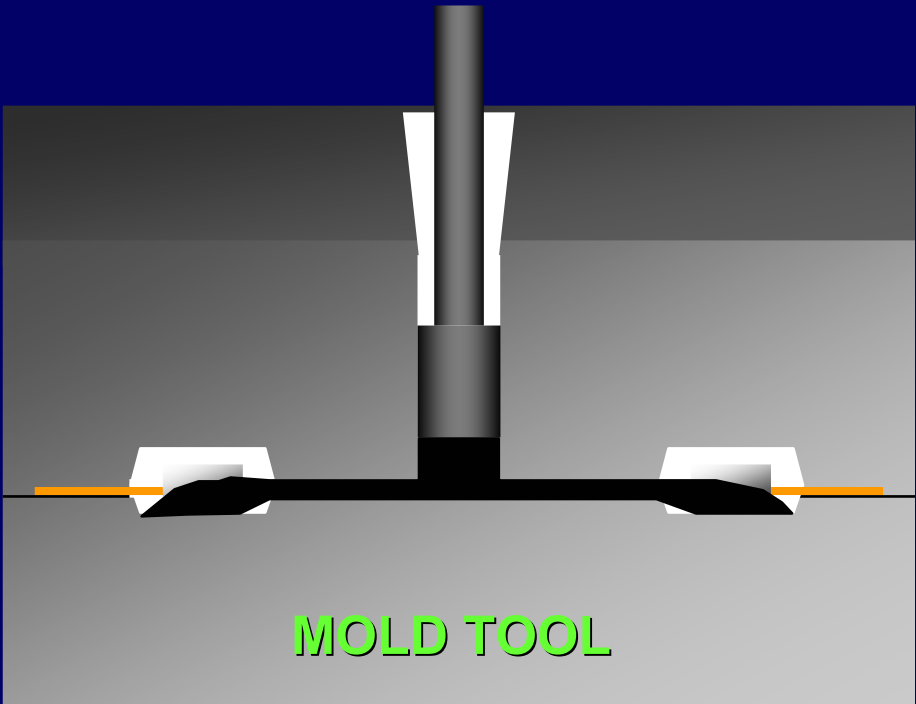


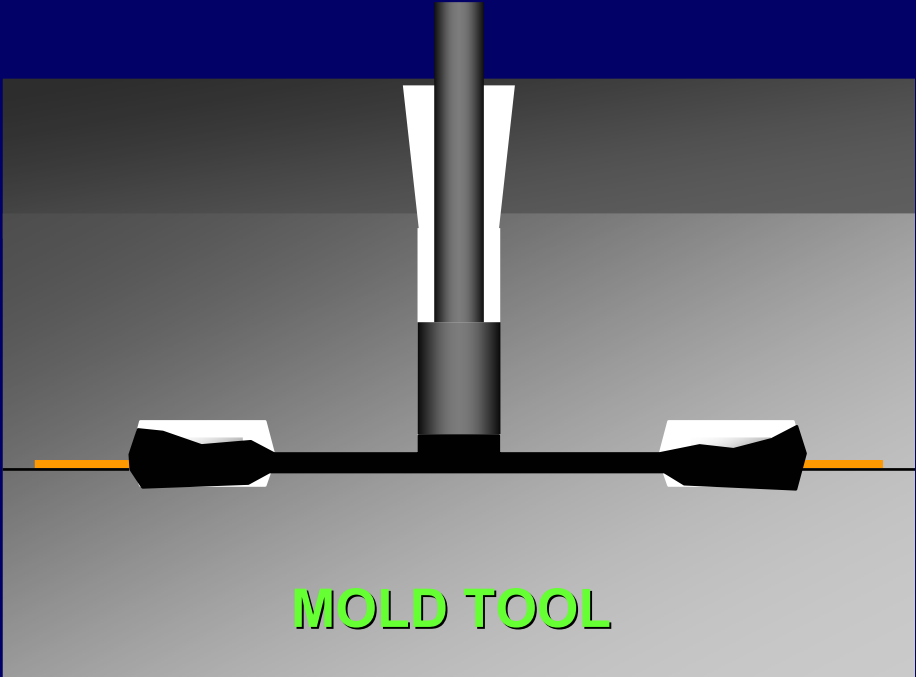


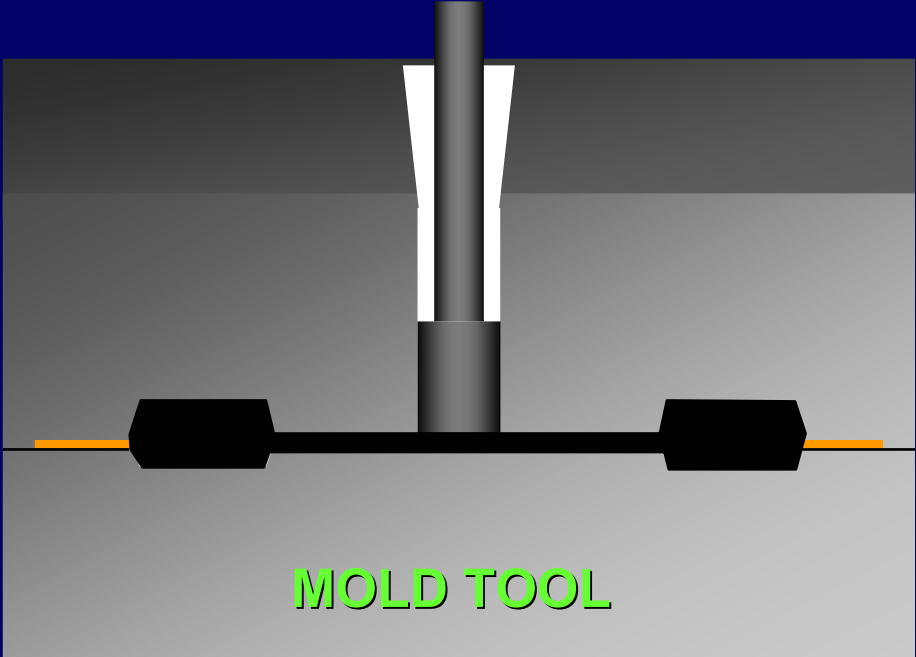




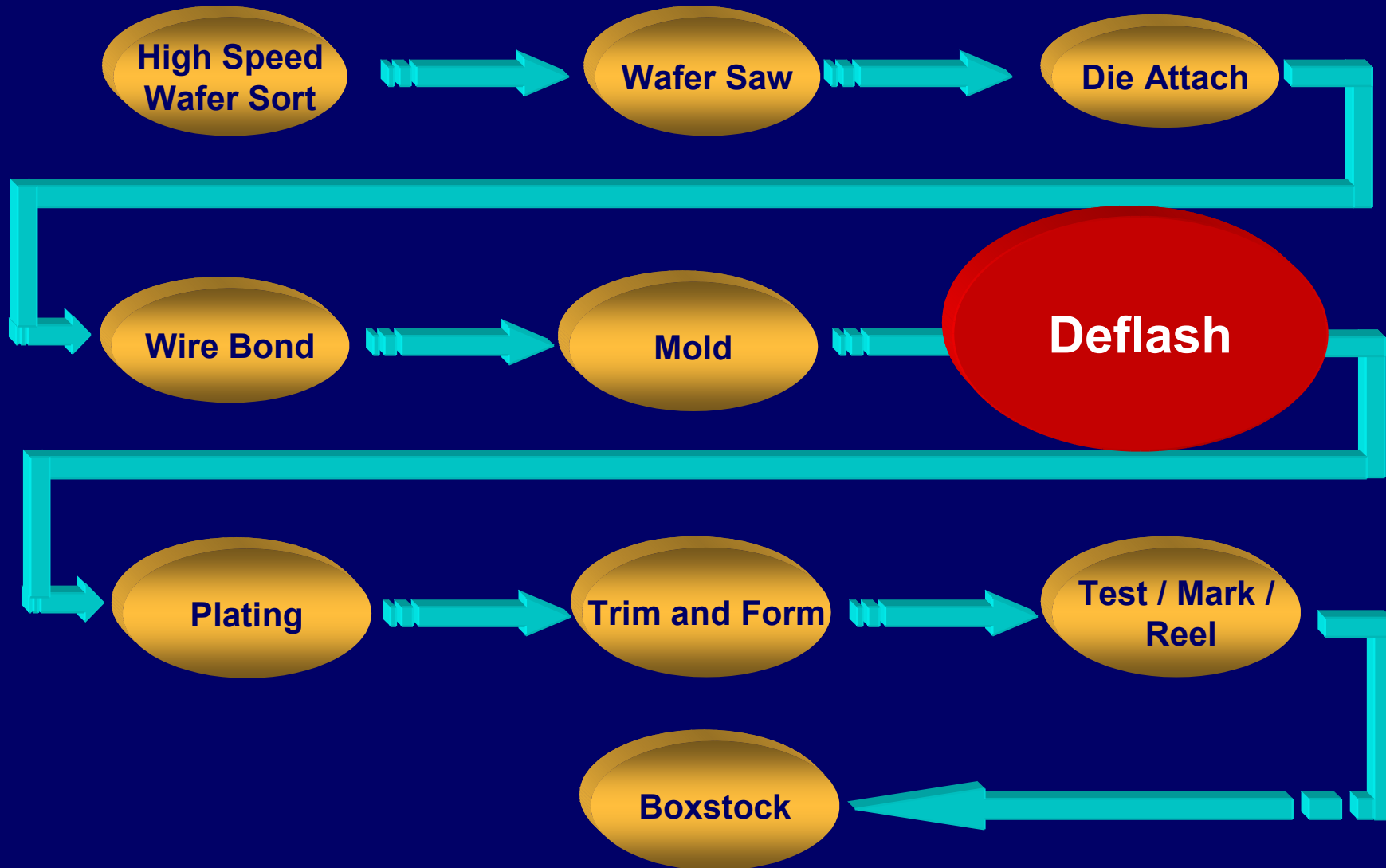






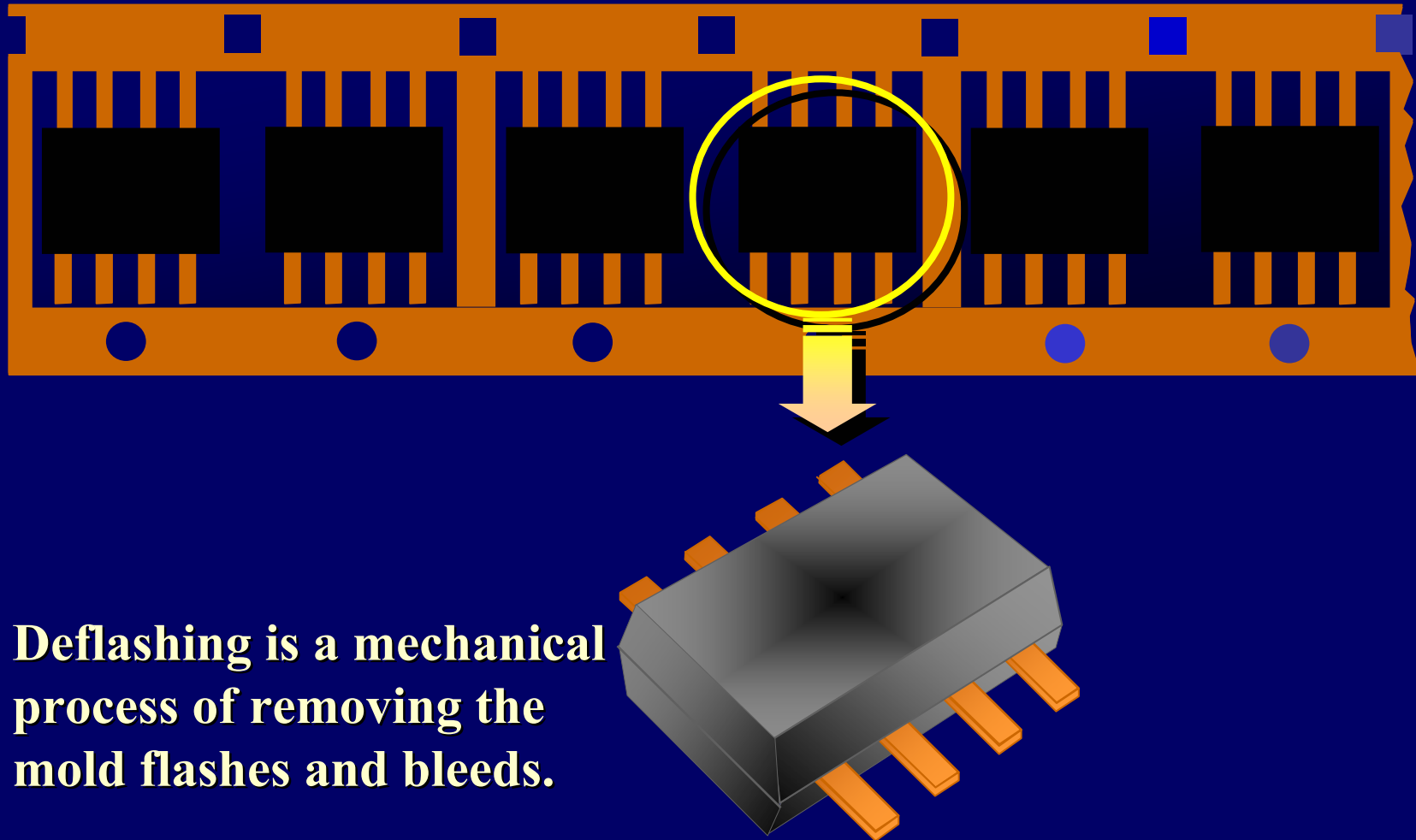


Manufacturing Technology

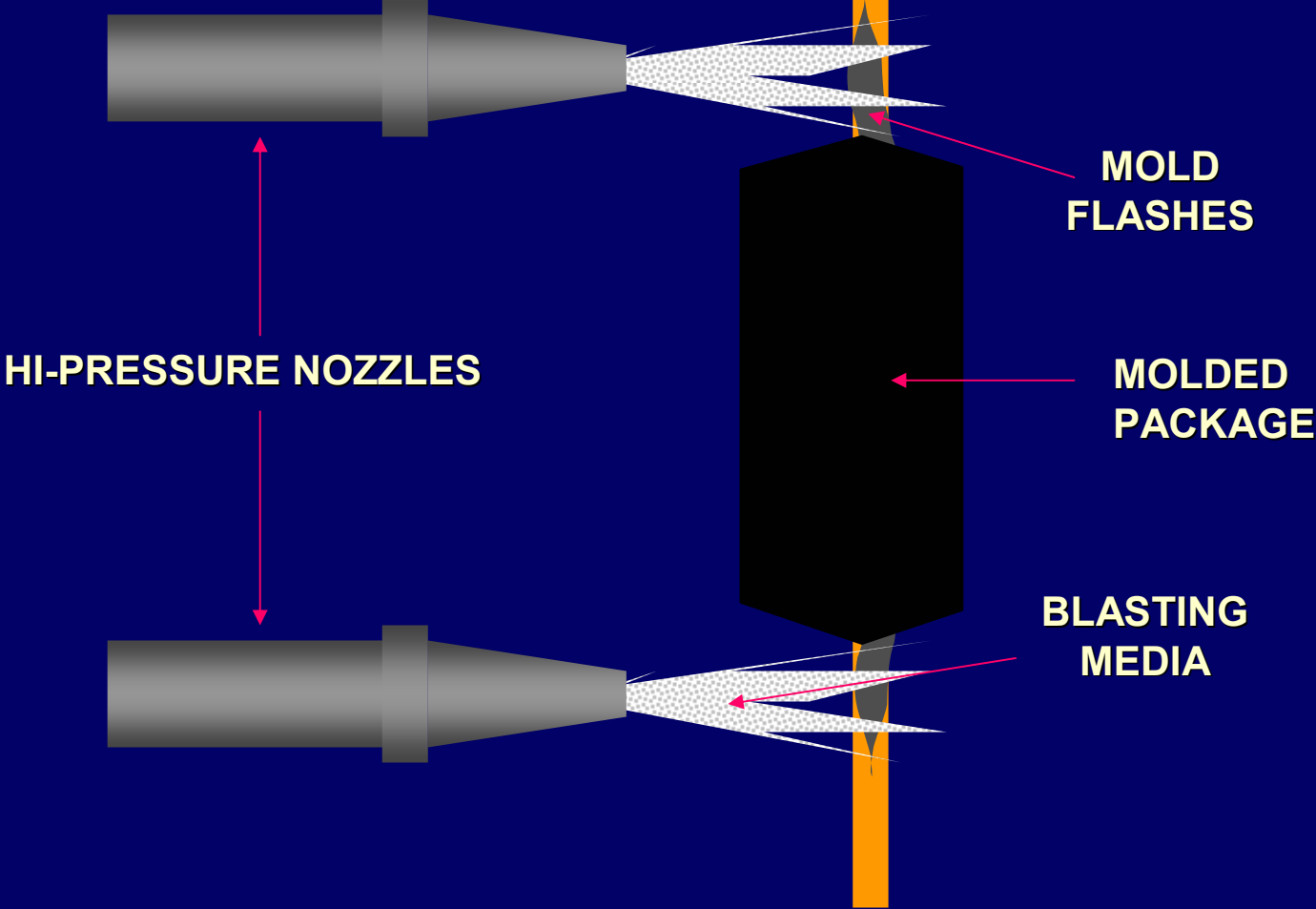


Deflash

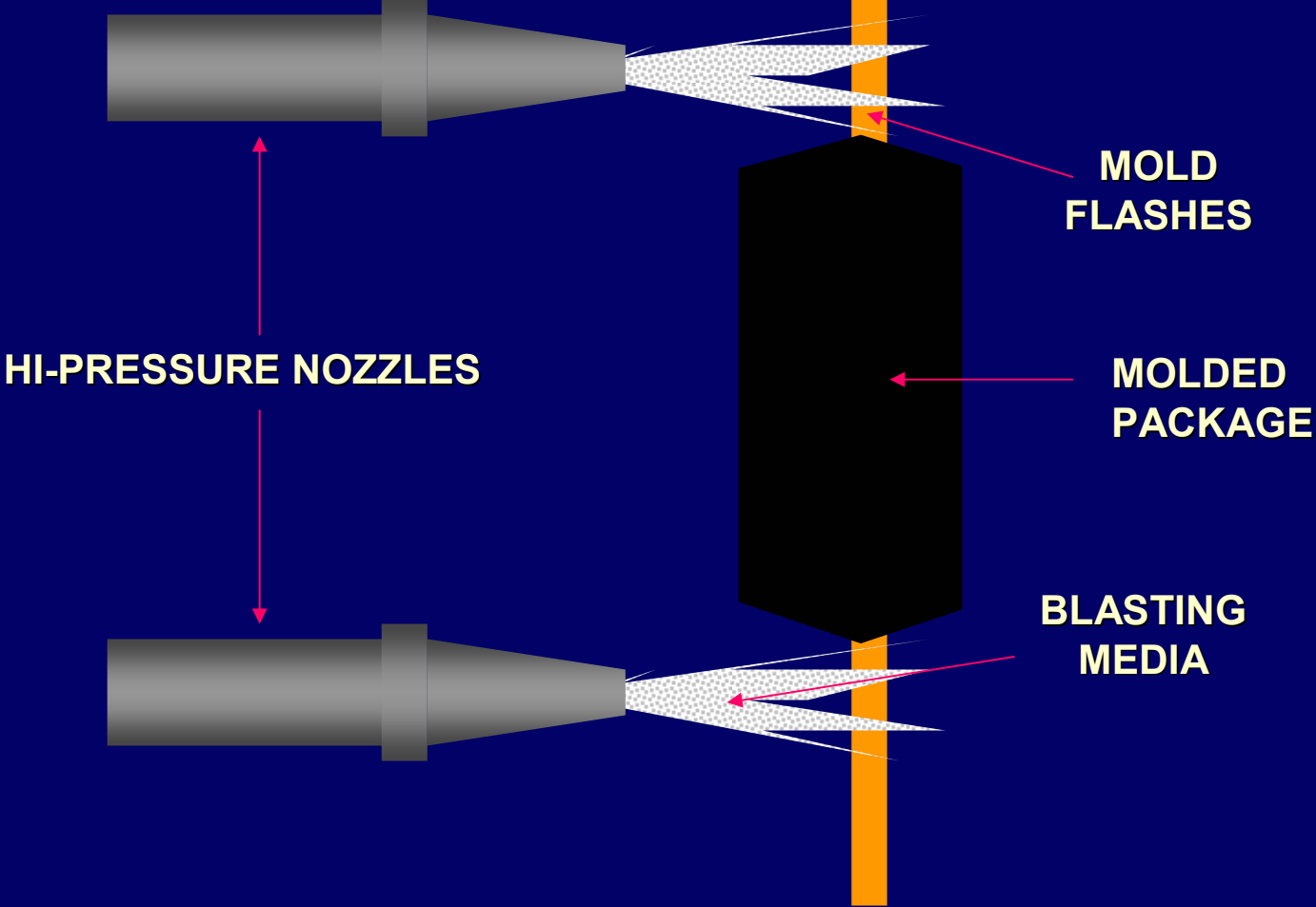
Semiconductor Manufacturing Process



Deflashing is a mechanical process of removing the mold flashes and bleeds.

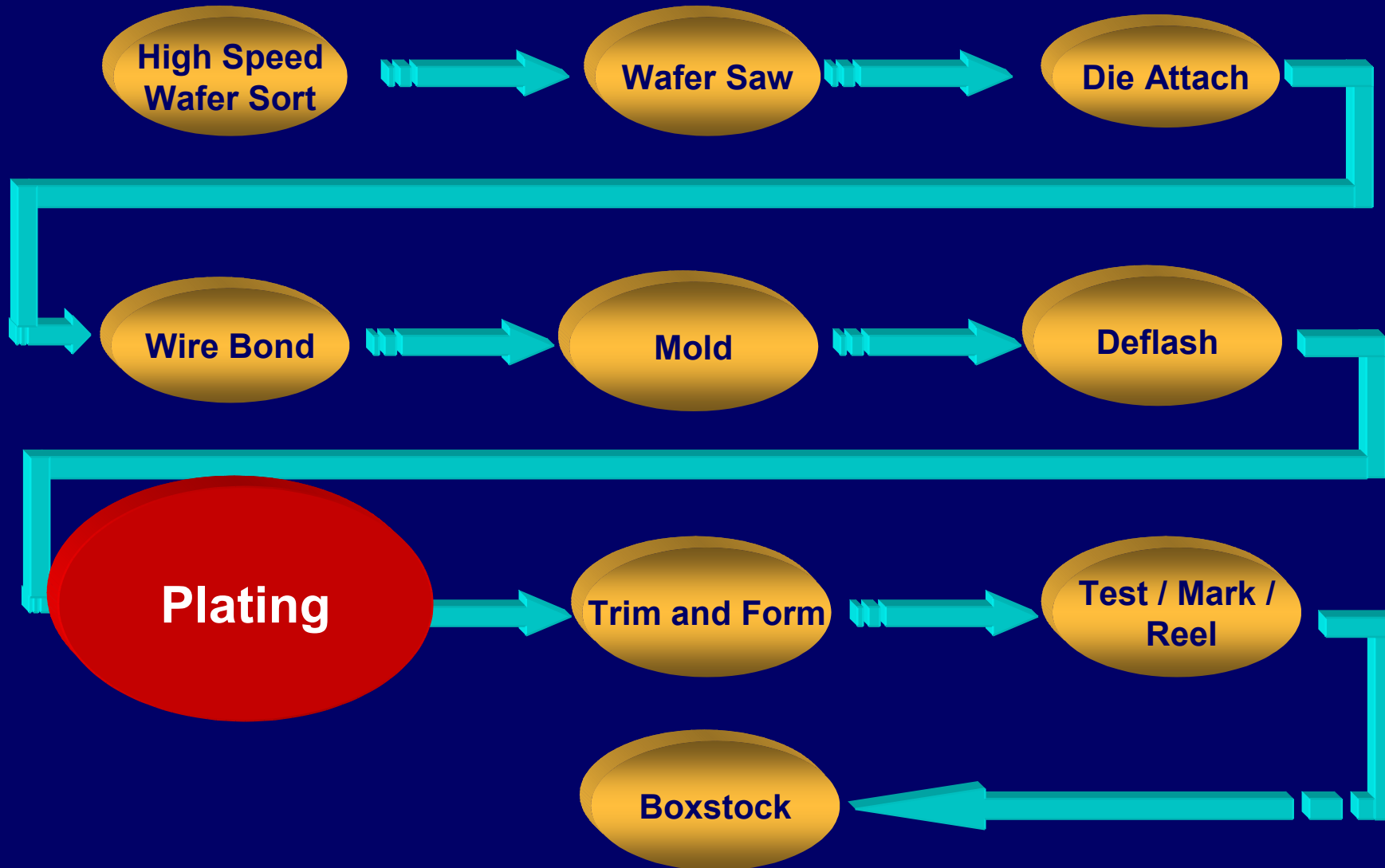


DEFLASH SET UP



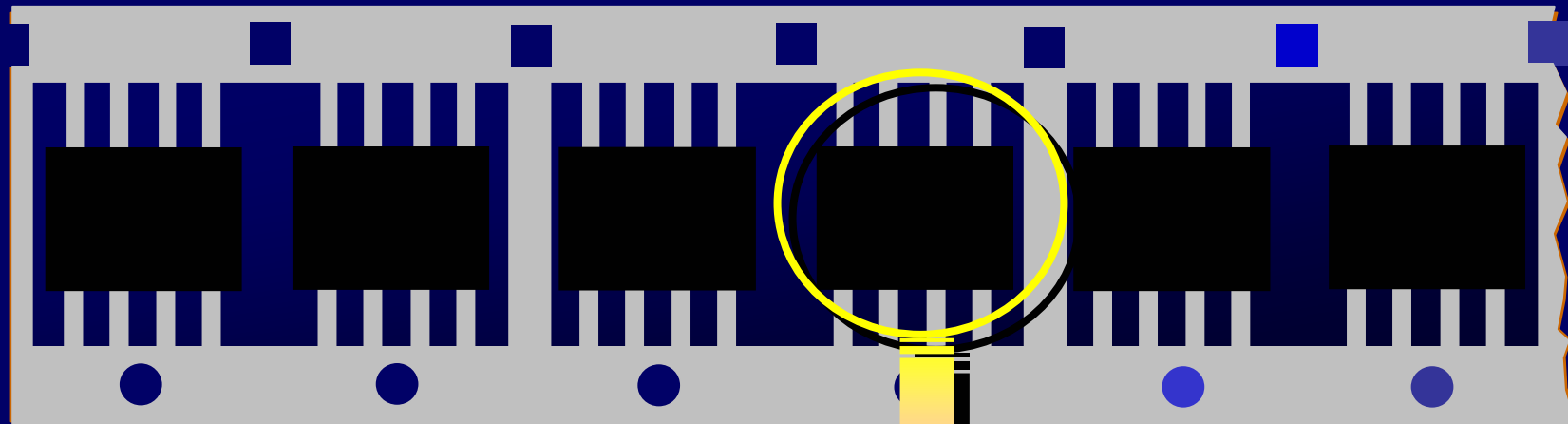
DEFLASH SET UP

Manufacturing Technology



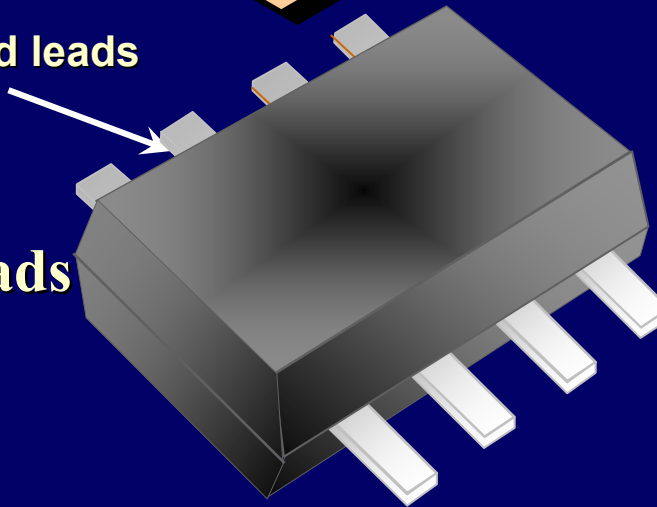
Solder Plating

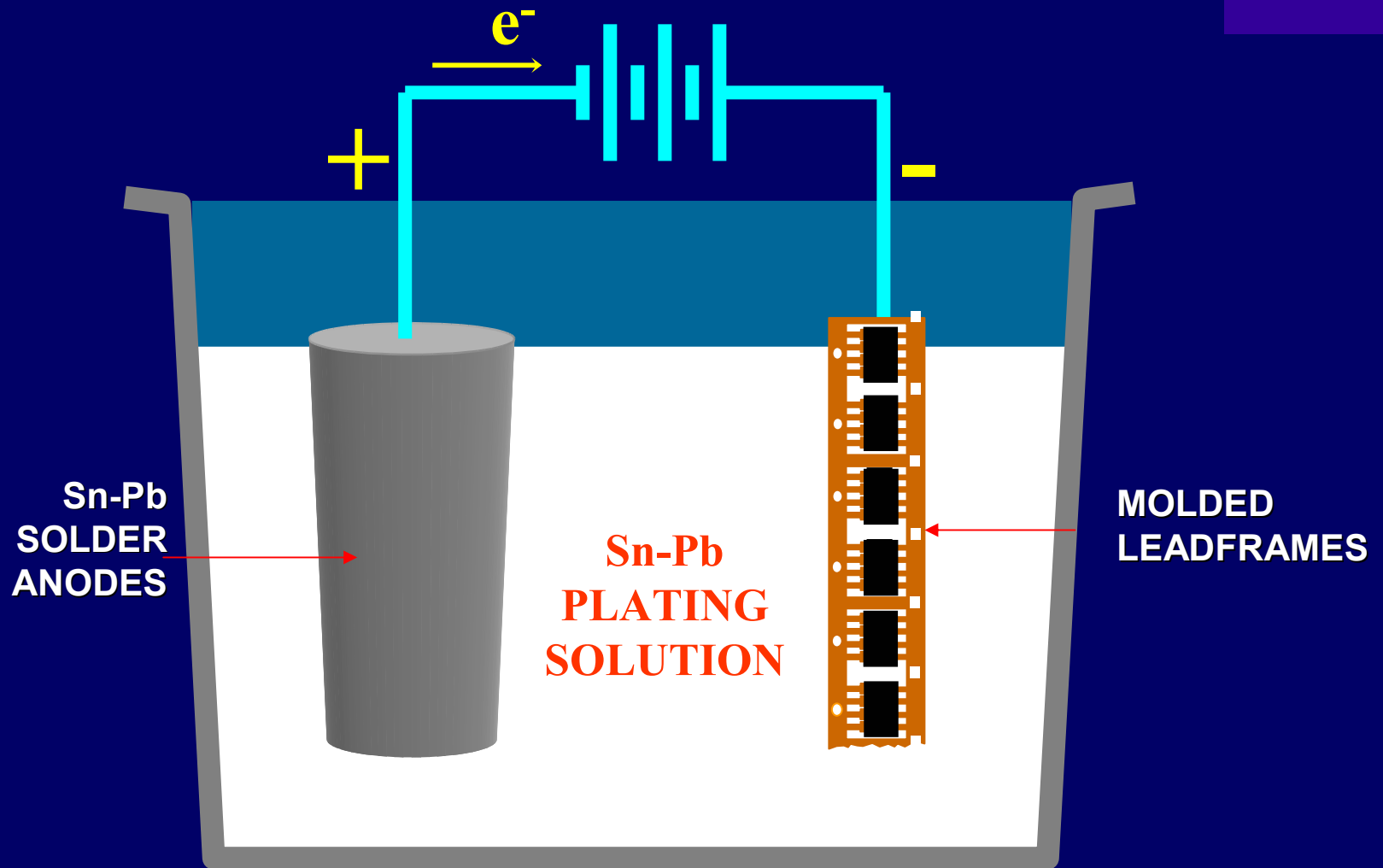
Semiconductor Manufacturing Process



Sn-Pb coated leads

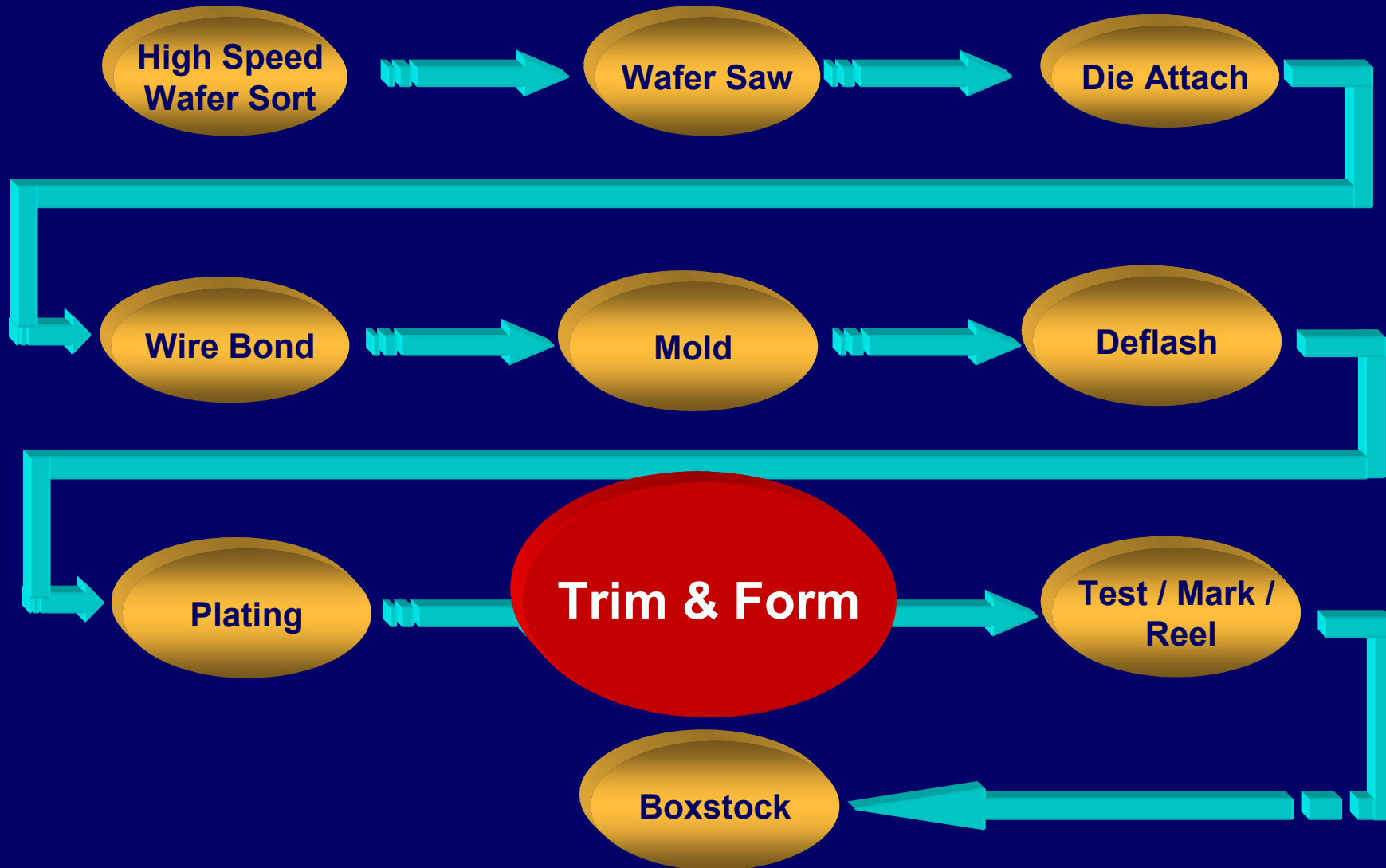
Solder plating is the process of coating the leads with Sn-Pb solder by electrolysis.





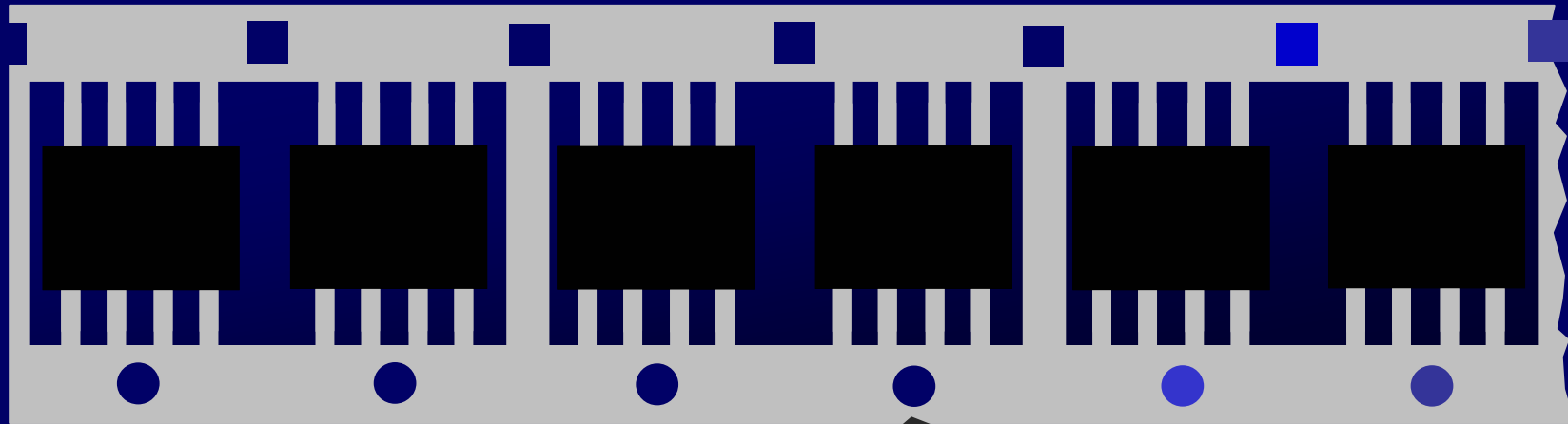
SOLDER PLATING SET UP

Manufacturing Technology

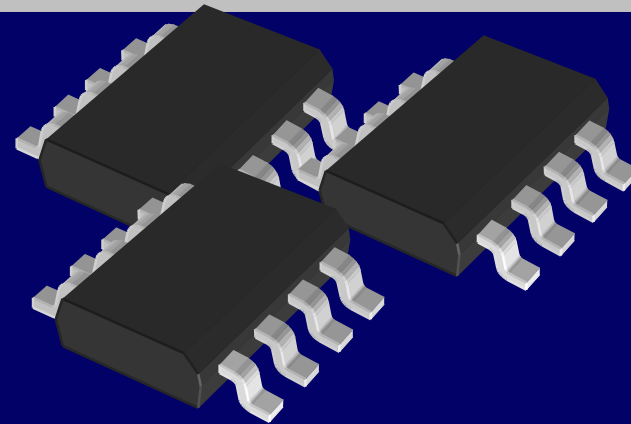


Trim and Form

Semiconductor Manufacturing Process

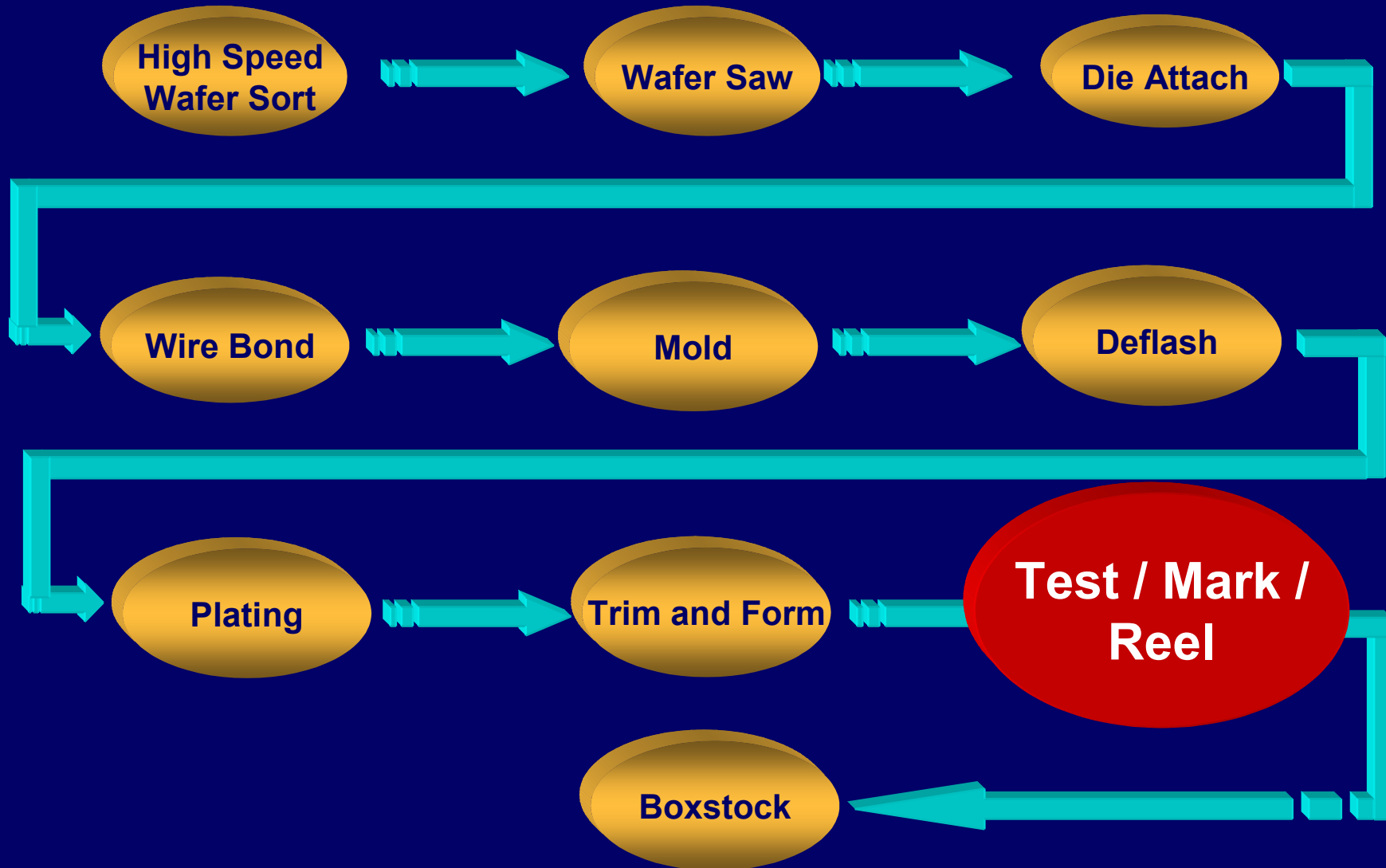


Trim & Form is a mechanical process of trimming and leadforming the leads.



Singulated packages/ units

Manufacturing Technology

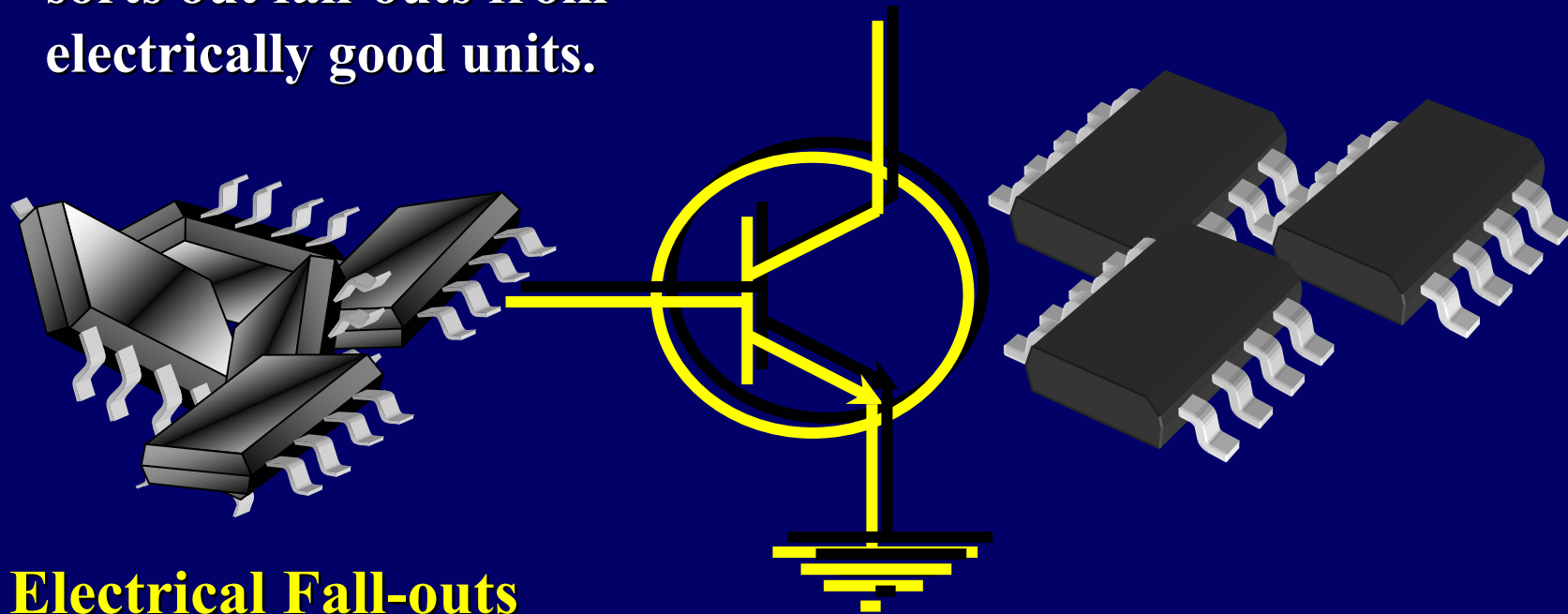


Electrical Testing

Semiconductor Manufacturing Process

Electrical testing process
sorts out fall-outs from
electrically good units.

Electrically good units

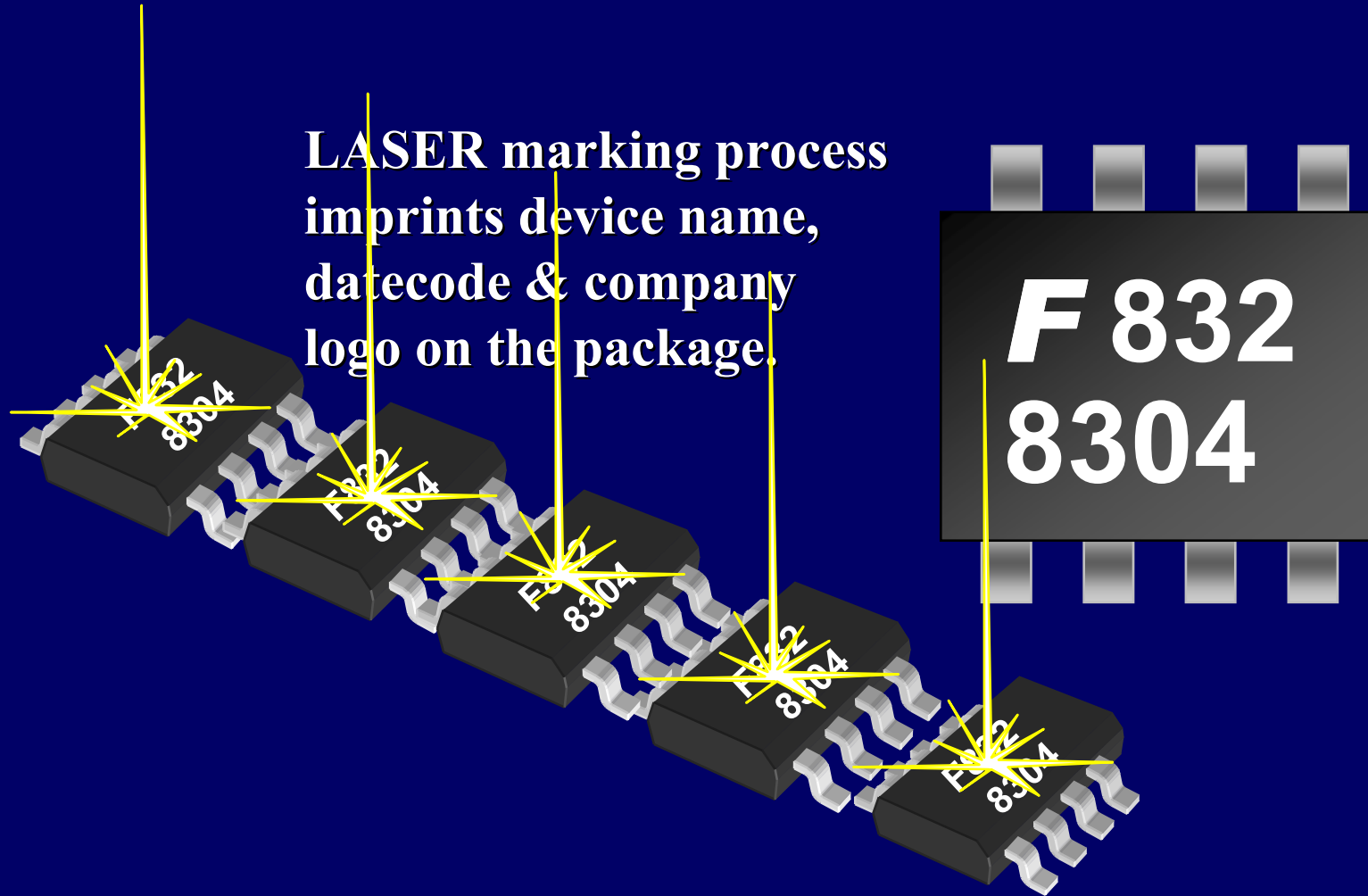


Electrical Fall-outs

Laser Marking

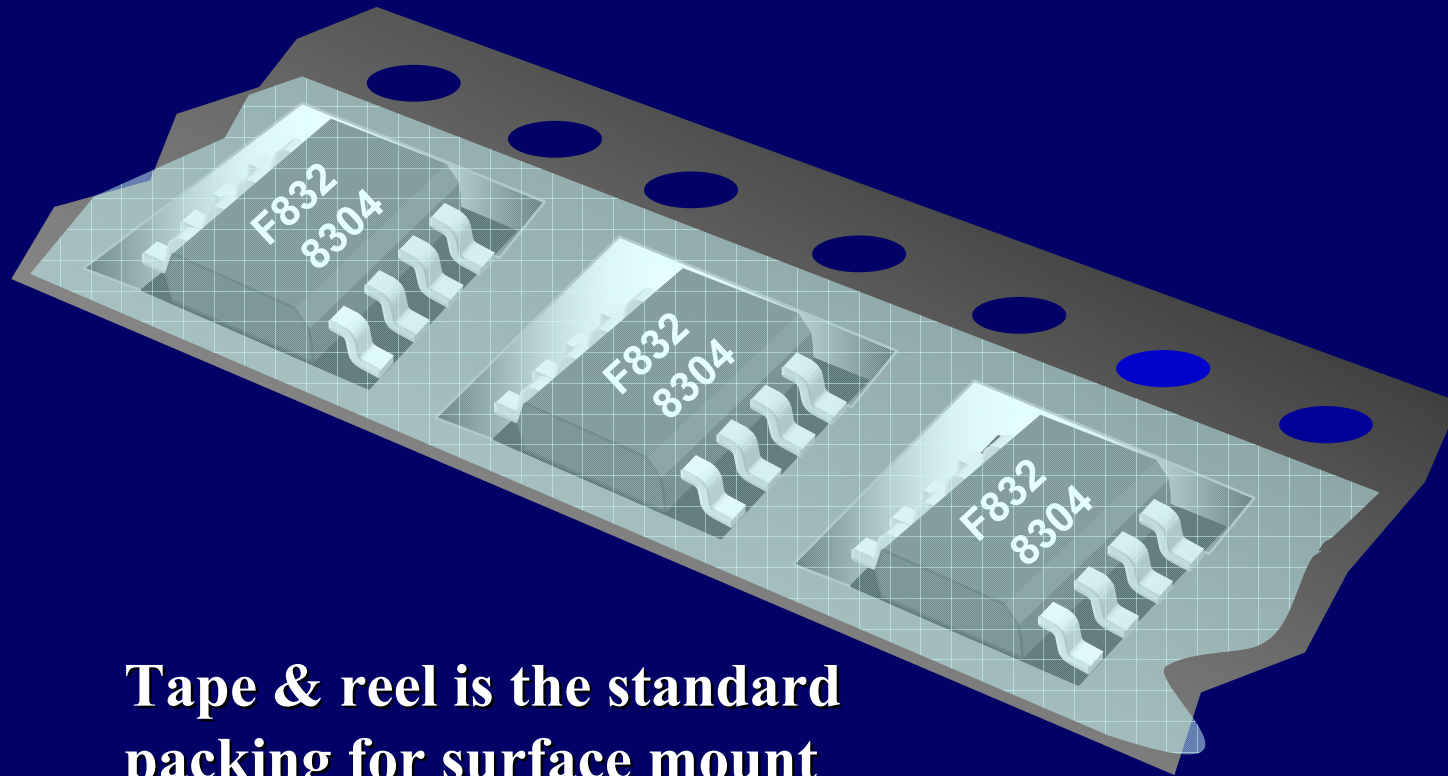
Semiconductor Manufacturing Process

LASER marking process
imprints device name,
datecode & company
logo on the package.



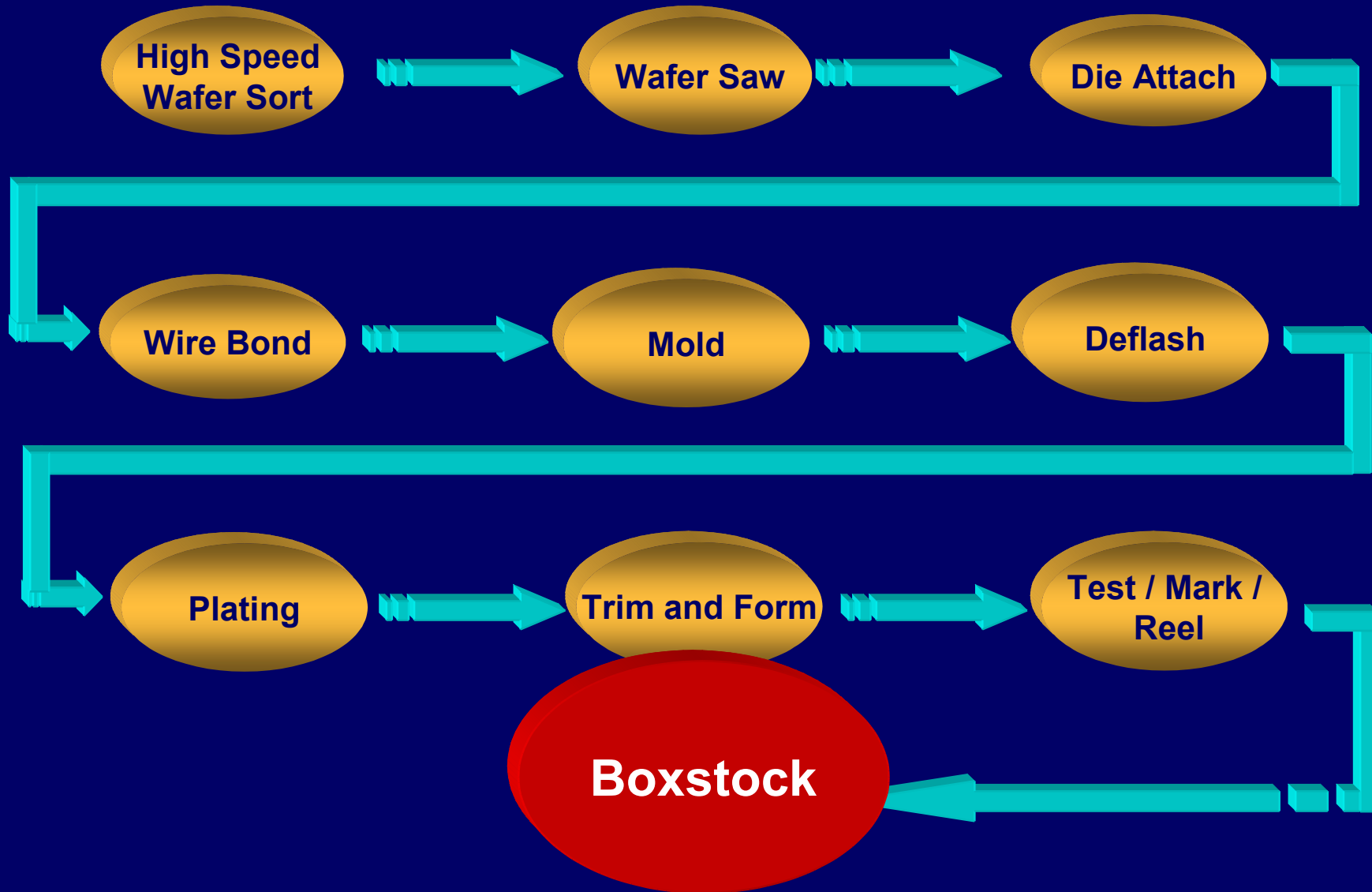
Tape and Reel Packing

Semiconductor Manufacturing Process



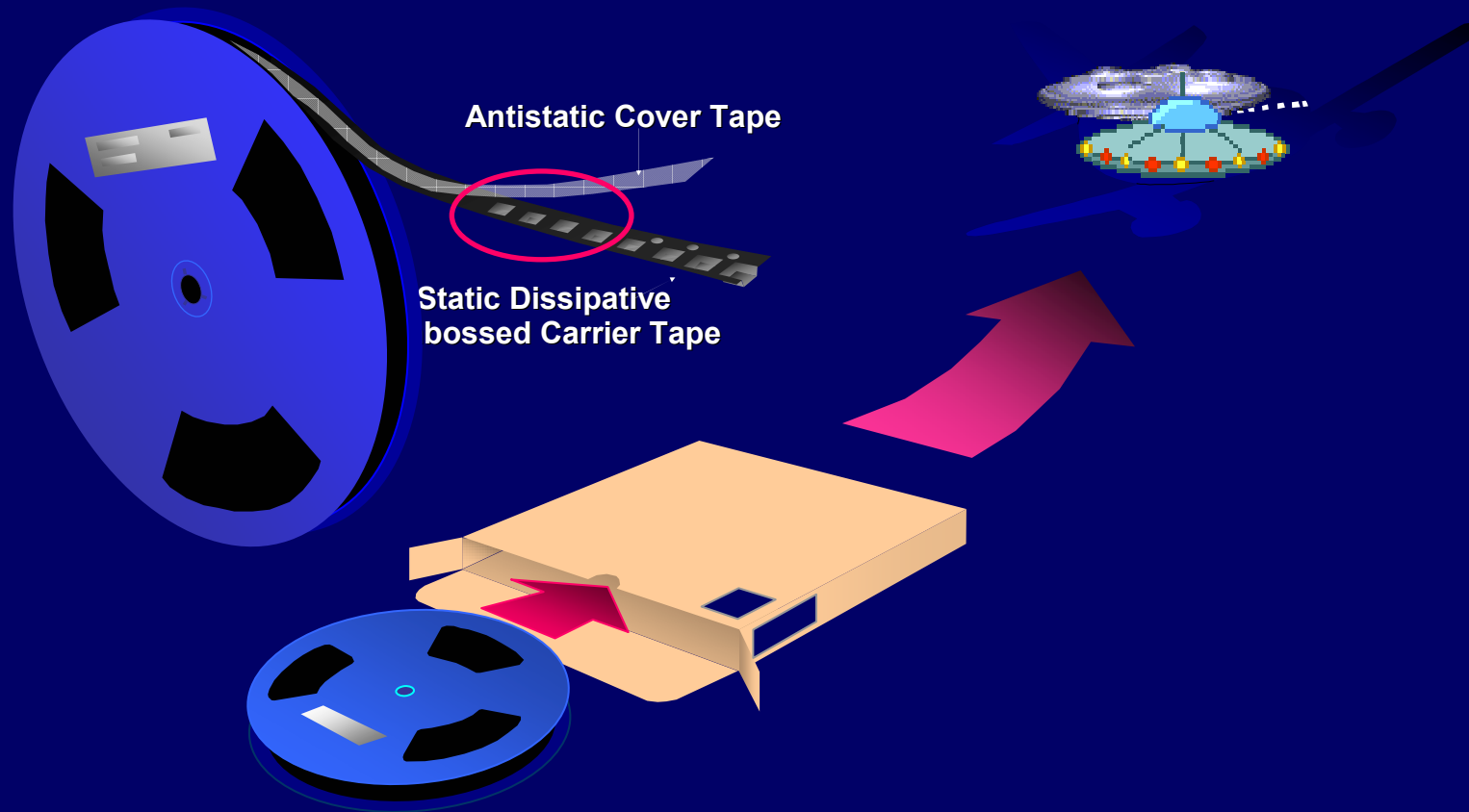
Tape & reel is the standard packing for surface mount packages/ devices.

Manufacturing Technology

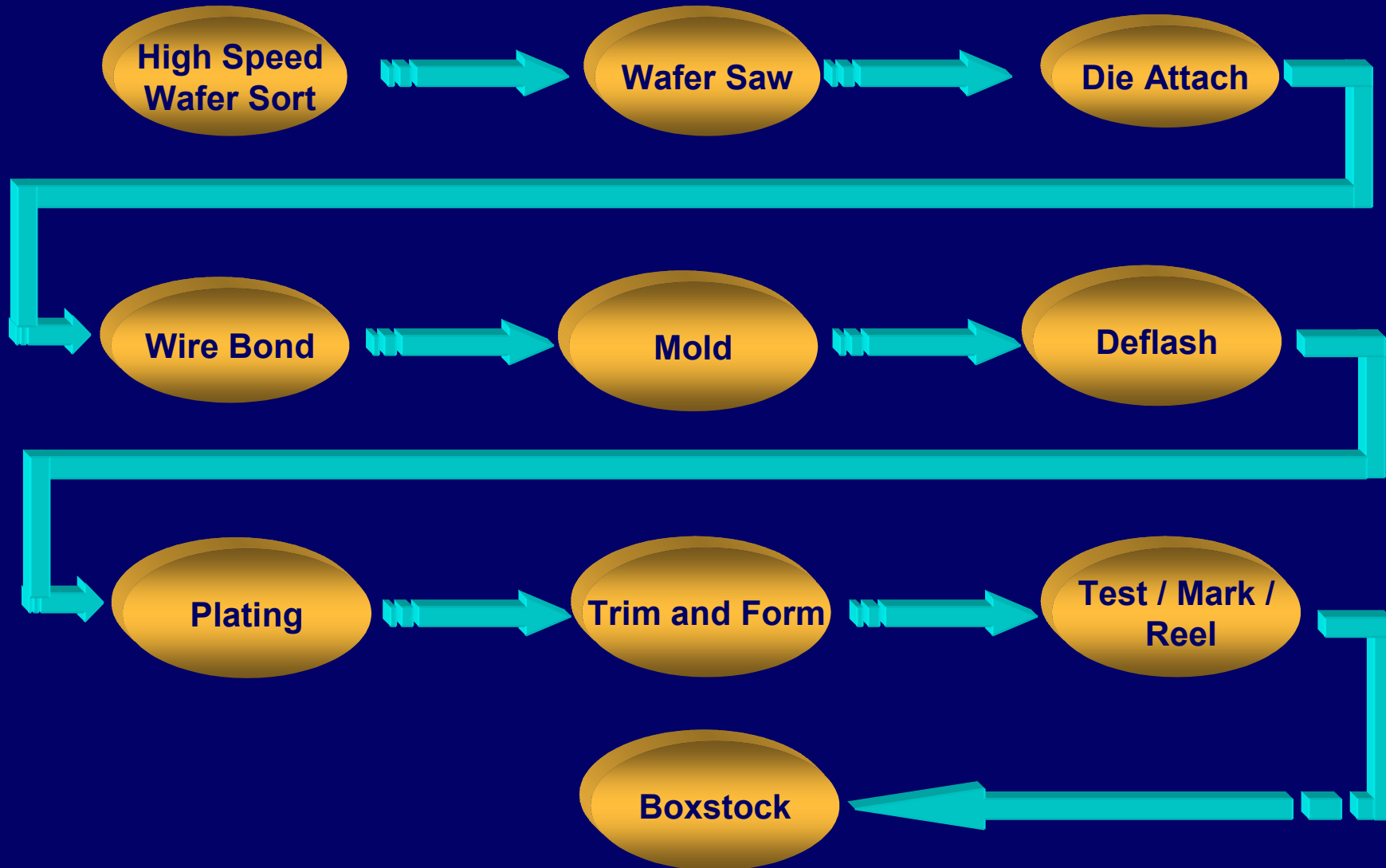


Tape and Reel Packing

Semiconductor Manufacturing Process



Manufacturing Technology





END